

# Detector Upgrades for the High Luminosity Large Hadron Collider

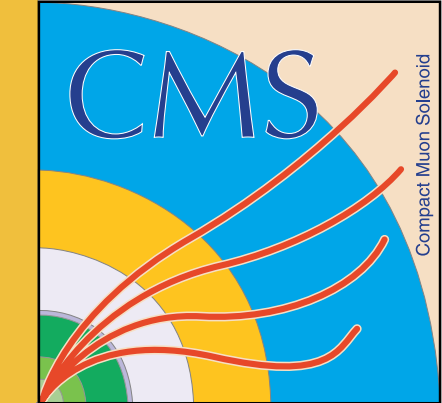
Rachel Yohay  
Florida State University  
Aspen Winter Conference

The Future of High Energy Physics: A New Generation, A New Vision  
March 26, 2024

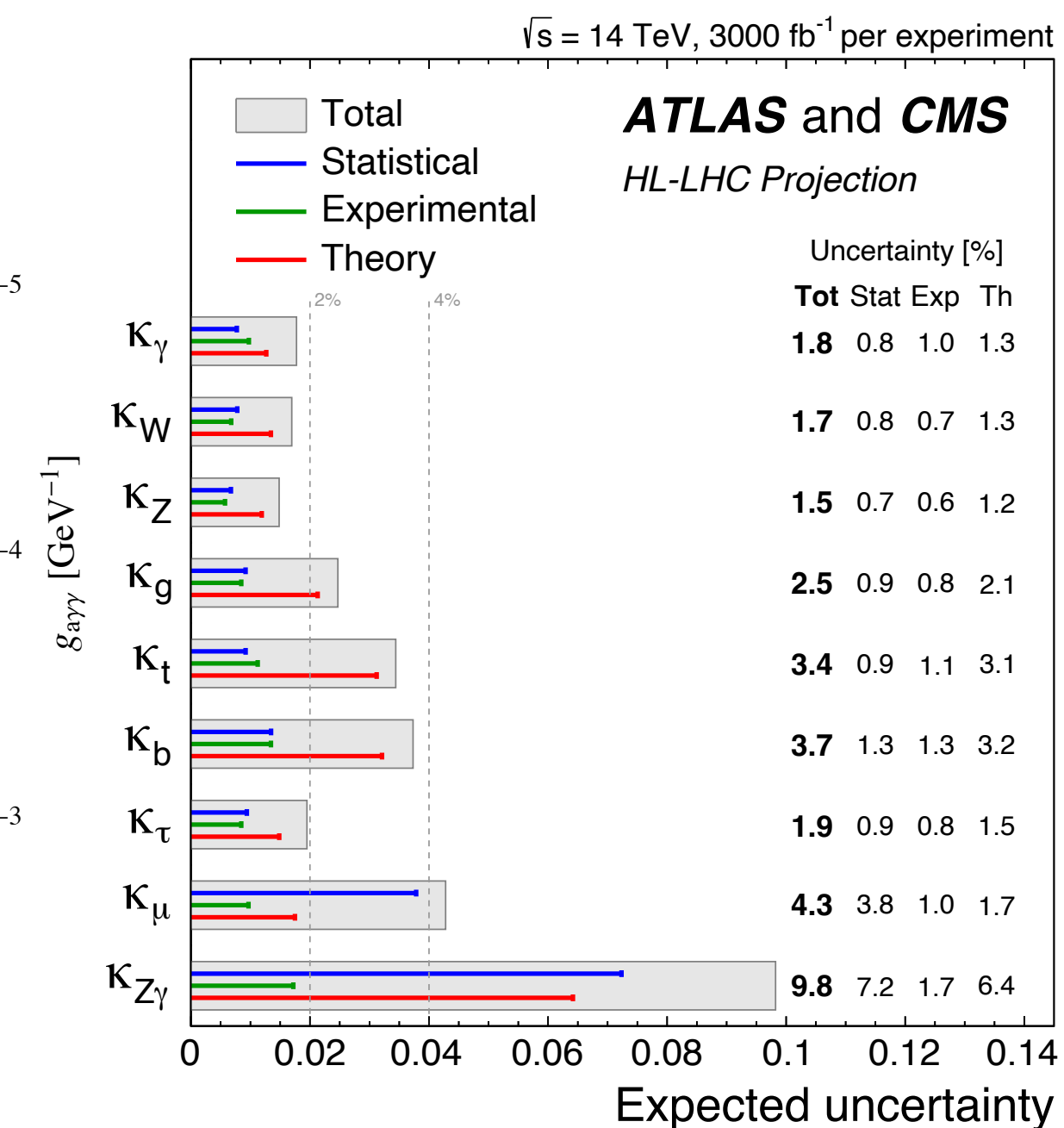
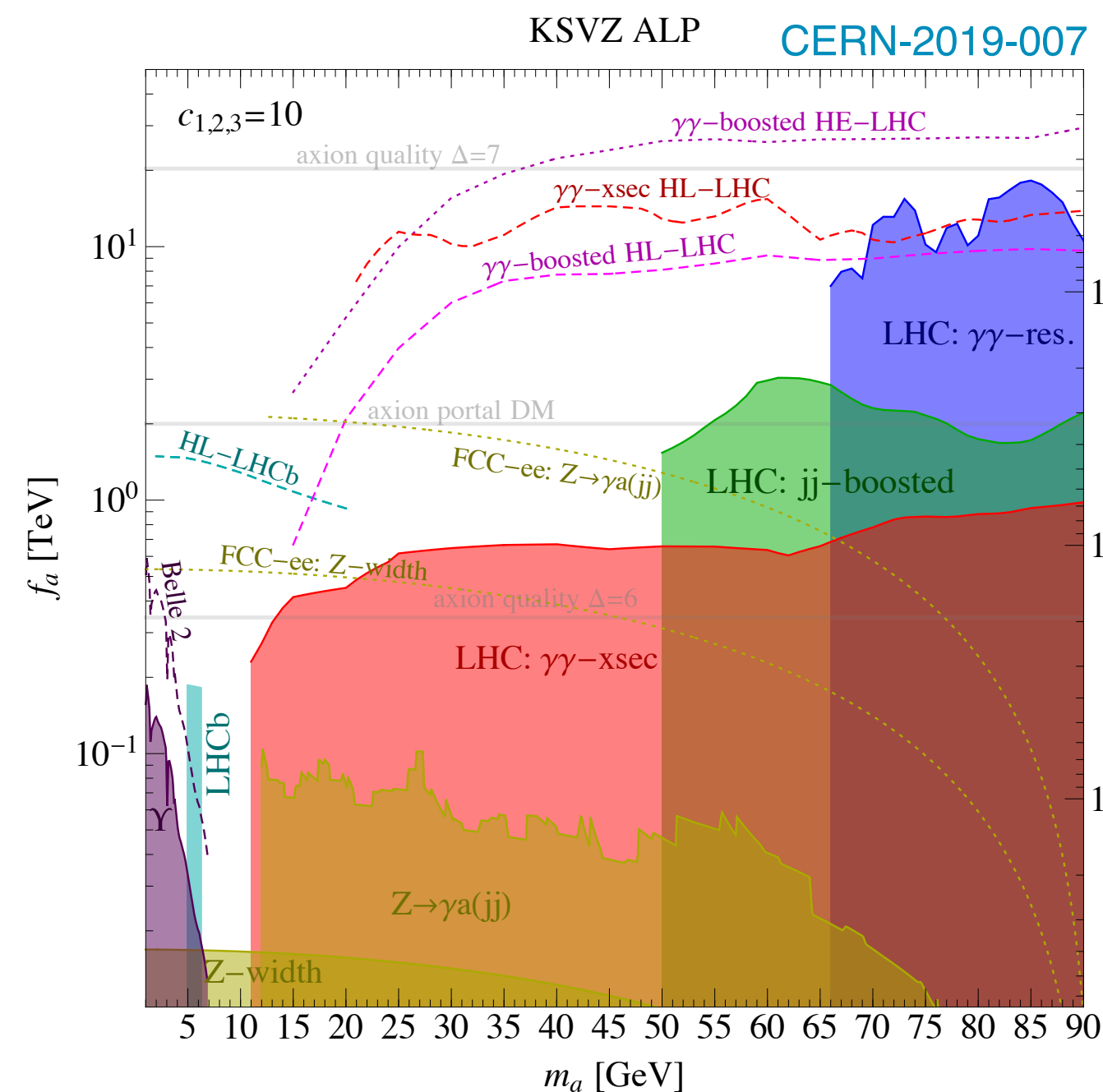


- Why the High Luminosity Large Hadron Collider (HL-LHC)?
- Challenges of the HL-LHC collision environment
- Detector design and technology requirements
- Highlights of the HL-LHC detector upgrades
  - Focus on CMS and ATLAS
- Conclusions

# Why the HL-LHC?



- Precision measurements of Higgs couplings: gauge, Yukawa, and self
- Higgs as a probe of physics beyond the Standard Model (BSM)
- Precision studies of electroweak symmetry via multiboson interactions or  $W$  mass measurement
- Rare BSM physics

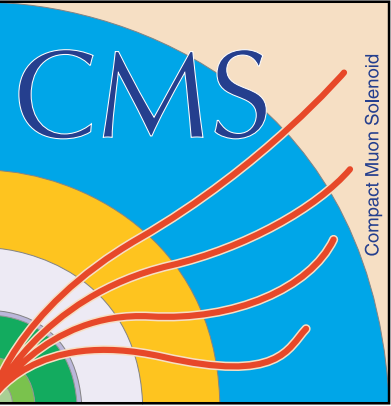


Process	$W^\pm W^\pm$	$WZ$	$WV$	$ZZ$	$WWW$	$WWZ$	$WZZ$
Final state	$l^\pm l^\pm jj$	$3ljj$	$ljjj$	$4ljj$	$3l3\nu$	$4l2\nu$	$5l\nu$
Precision	6%	6%	6.5%	10–40%	11%	27%	36%
Significance	$> 5\sigma$	$> 5\sigma$	$> 5\sigma$	$> 5\sigma$	$> 5\sigma$	$3.0\sigma$	$3.0\sigma$

CERN-LPCC-2018-03

CERN-LPCC-2018-04

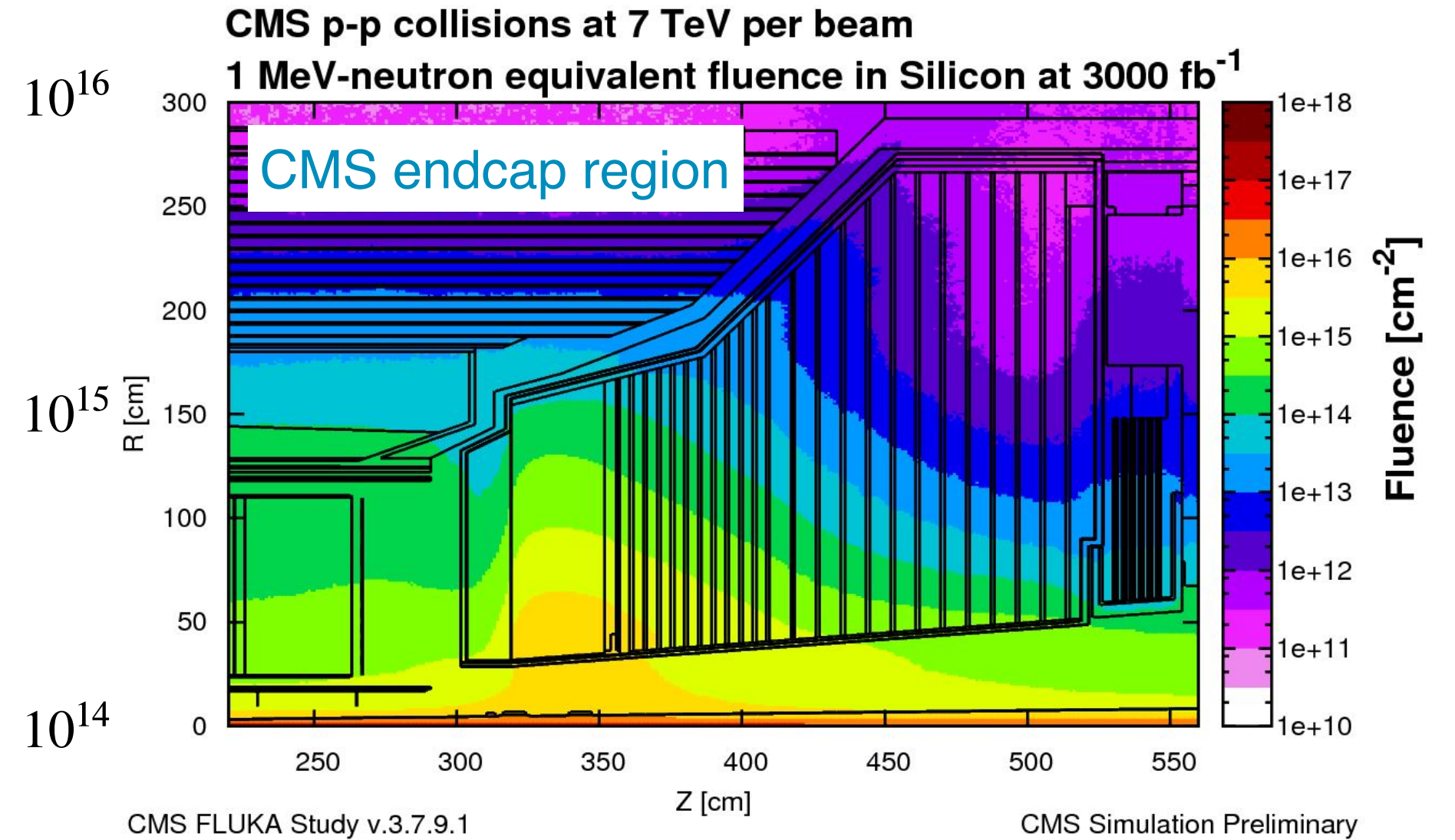
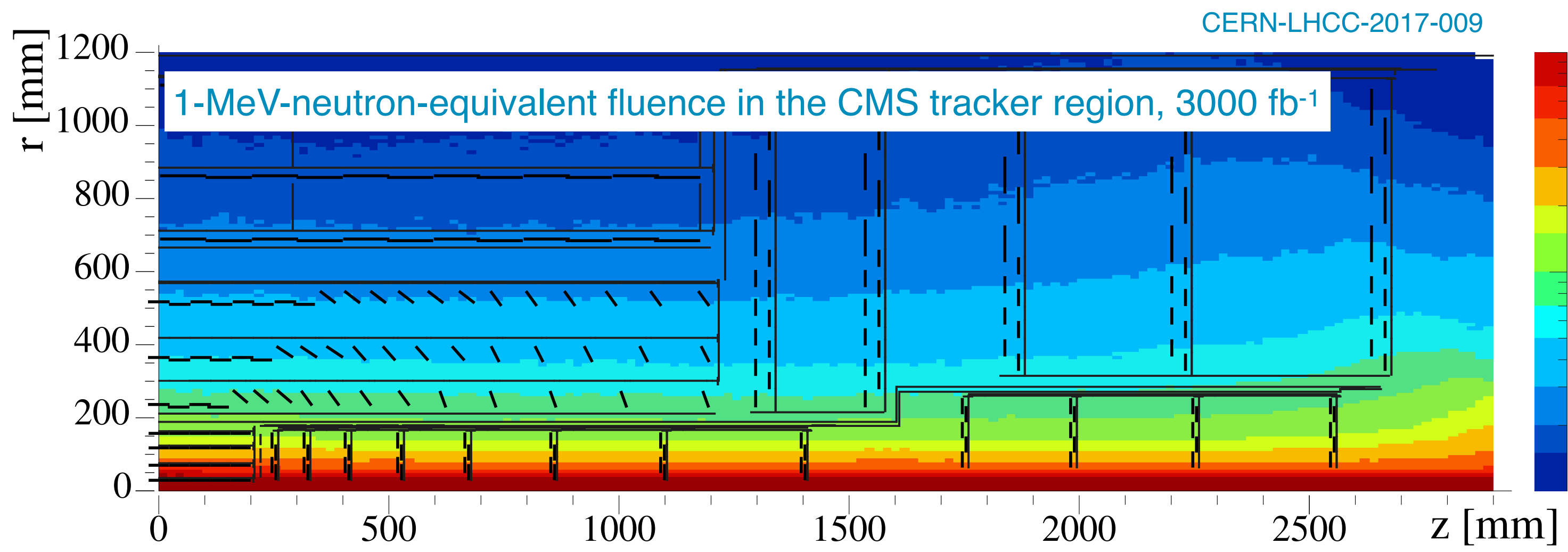
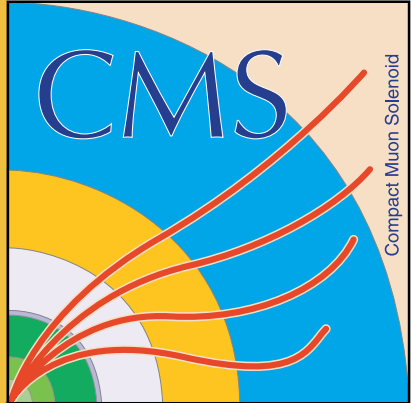
# Why the HL-LHC?



<https://voisins.web.cern.ch/en/high-luminosity-lhc-hl-lhc>

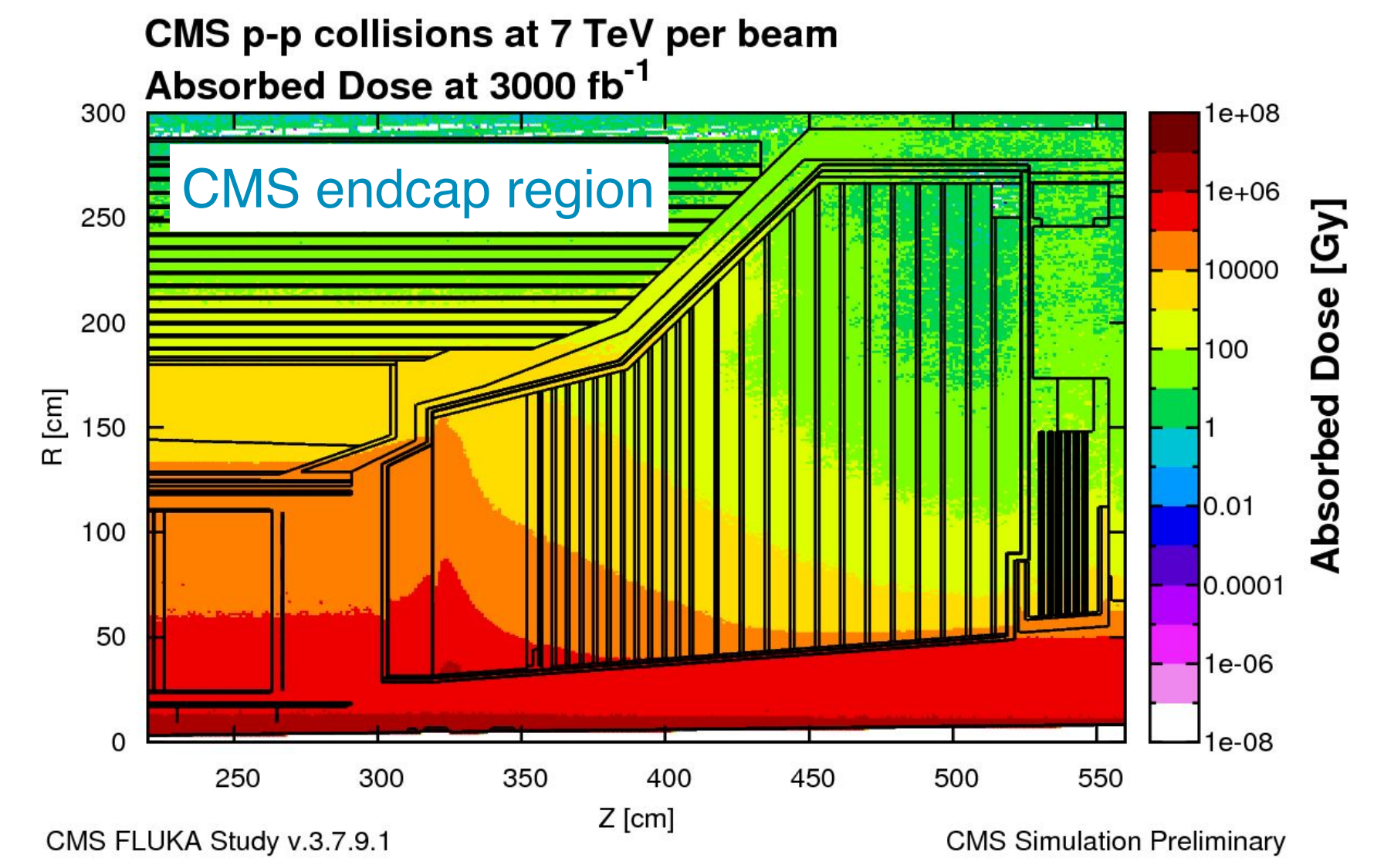


# Challenges of the HL-LHC collision environment

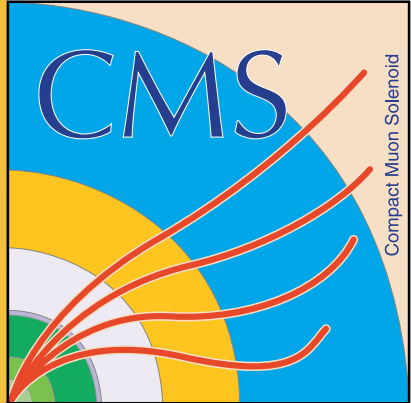


	Baseline	Stretch
$L_{inst}$ (cm <sup>-2</sup> s <sup>-1</sup> )	$5 \times 10^{34}$	$7.5 \times 10^{34}$
$L_{int}$ (fb <sup>-1</sup> )	3000	4000
Avg. pileup (PU)	140	200
Fluence* (n <sub>eq</sub> /cm <sup>2</sup> )	$\sim 2 \times 10^{16}$ max	$\sim 2.5 \times 10^{16}$ max
Dose* (MGy)	$\sim 12$ max	$\sim 15$ max

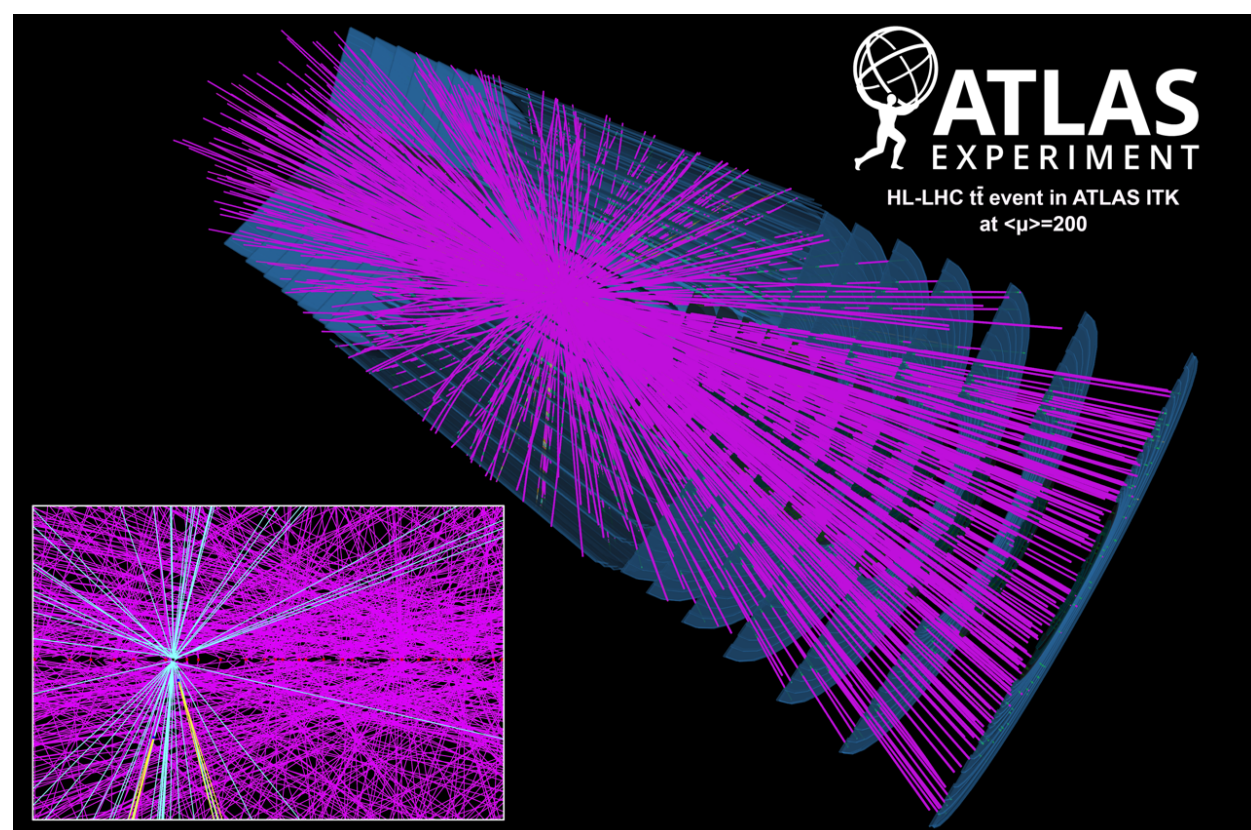
\*In CMS, similar for ATLAS



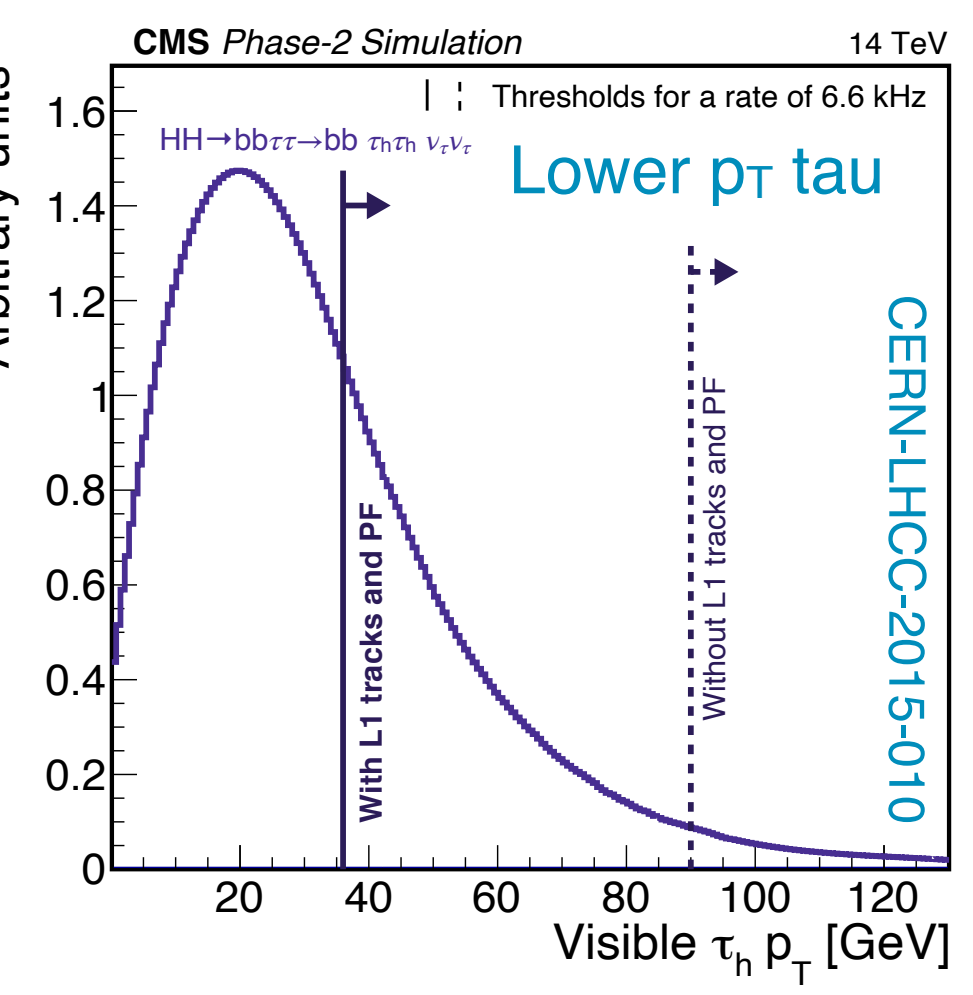
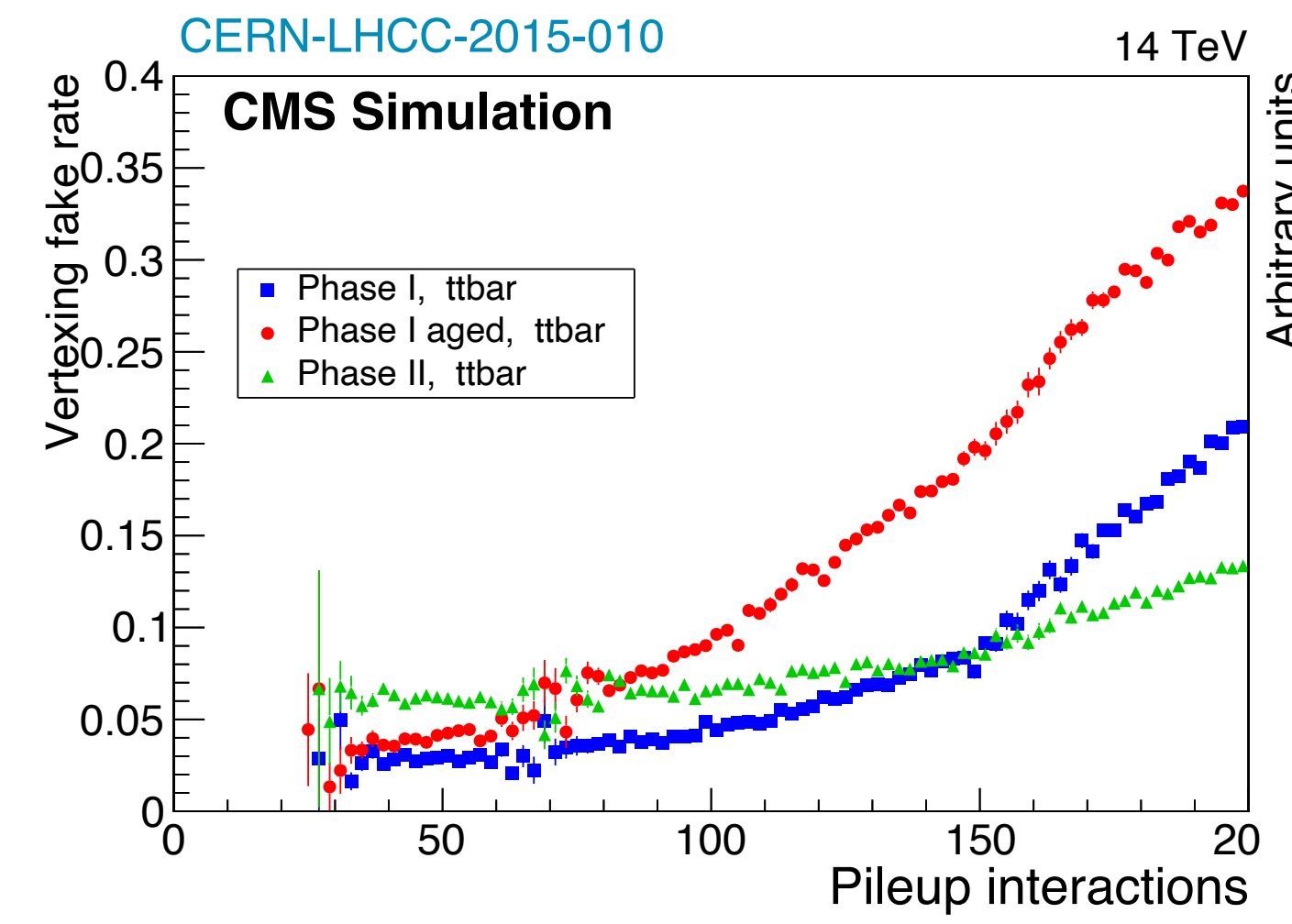
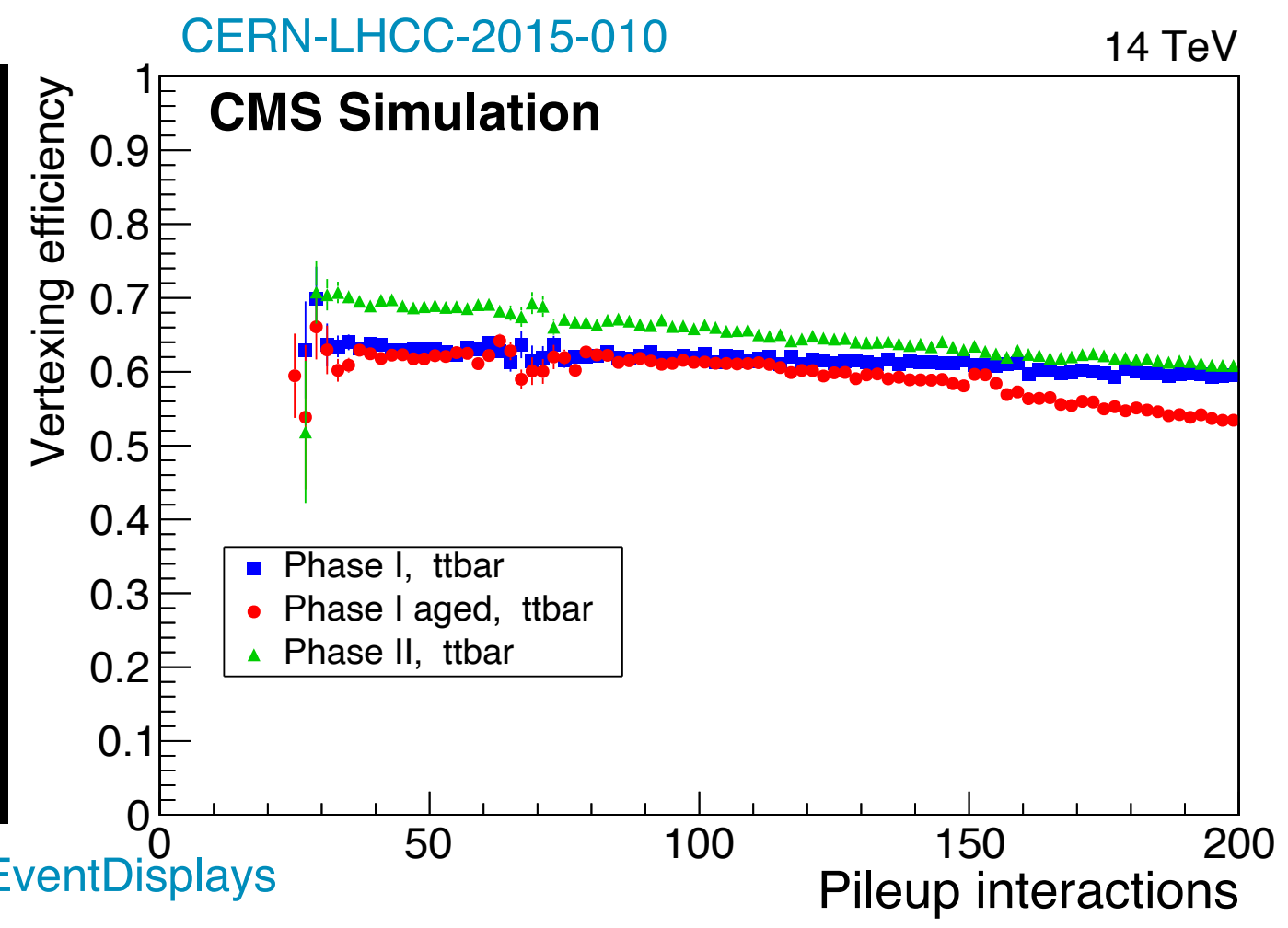
# Challenges of the HL-LHC collision environment



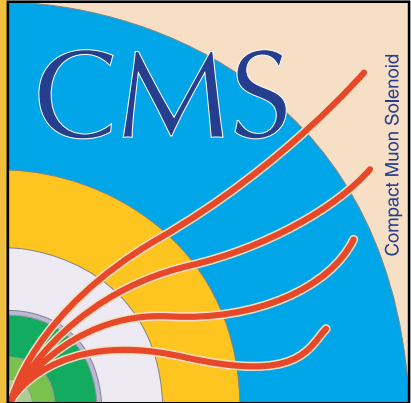
- $\langle \text{PU} \rangle = 140\text{-}200$  pp interactions per 25 ns bunch crossing (BX)
- Vertex and track reconstruction algorithms less discriminating
- Existing trigger and readout bandwidth constraints imply tighter selection requirements to increase purity at the cost of signal acceptance



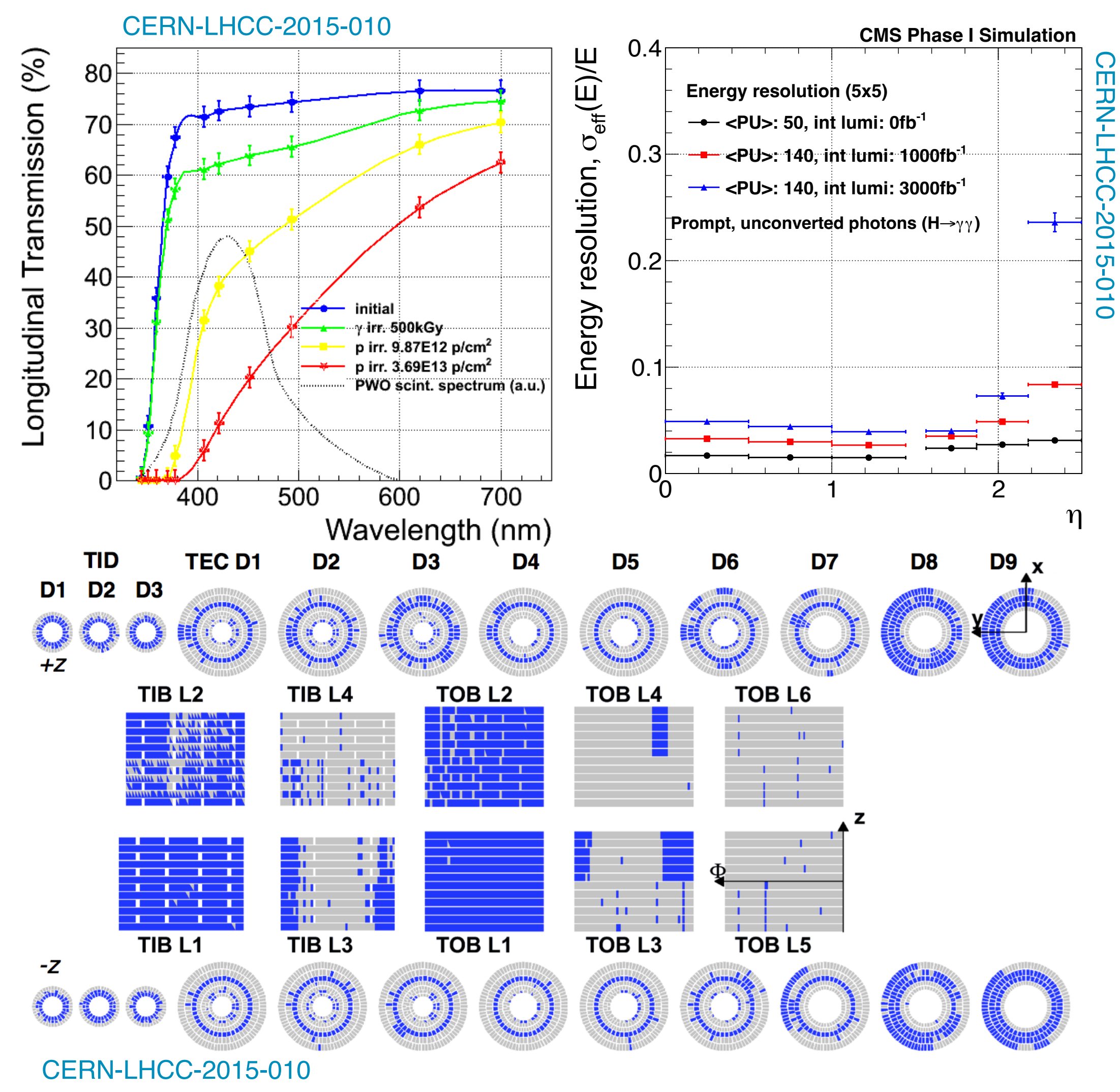
<https://twiki.cern.ch/twiki/bin/view/AtlasPublic/UpgradeEventDisplays>

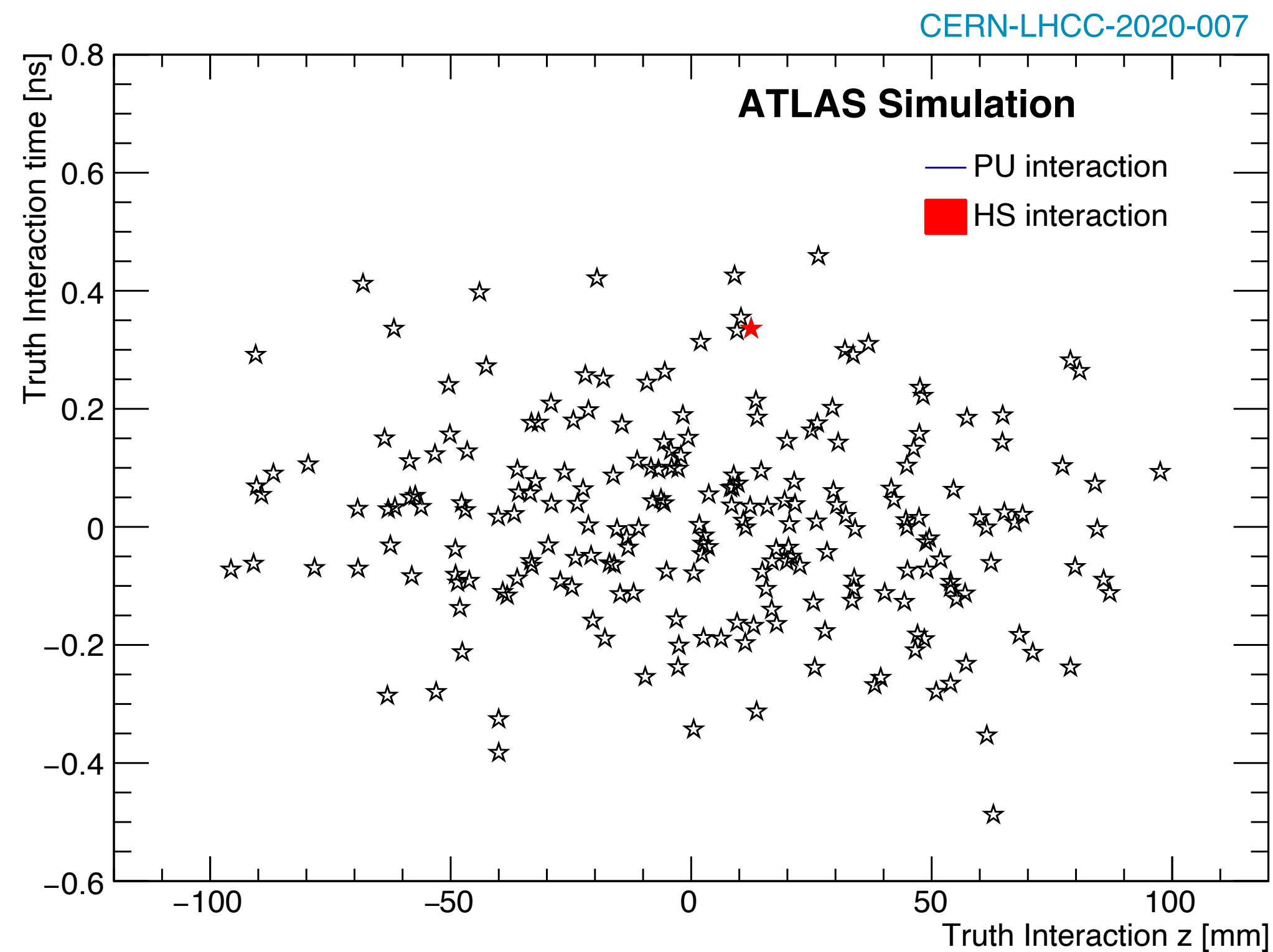


# Challenges of the HL-LHC collision environment



- Accelerated aging in the general purpose detectors
- Detector materials need to withstand another order of magnitude in dose and fluence
- Need to maintain optically transparent materials (e.g. scintillators)
- Need to manage leakage current and charge trapping in silicon sensors, dark count rate in silicon photomultipliers
- Need to manage single event upsets in front end ASICs

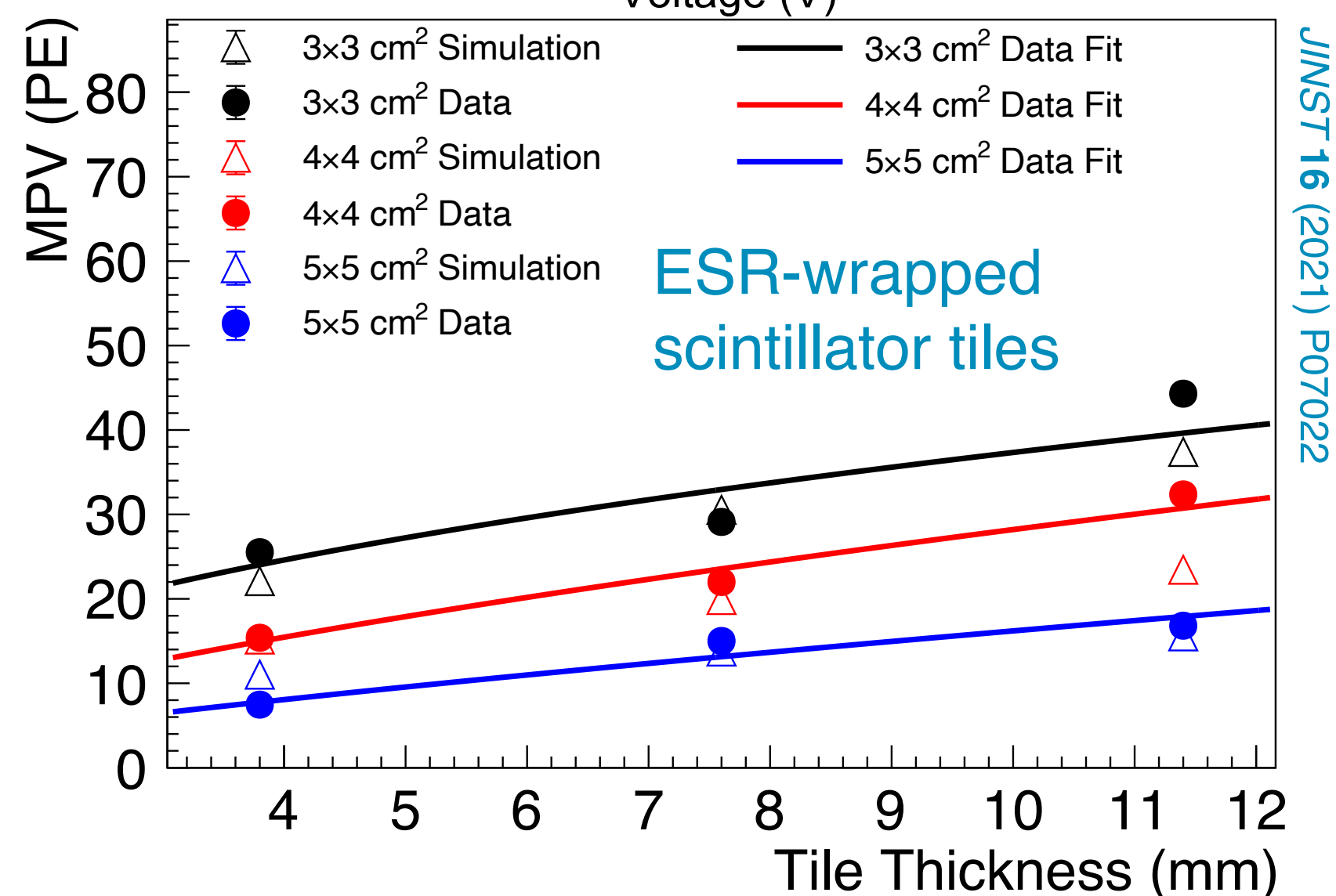
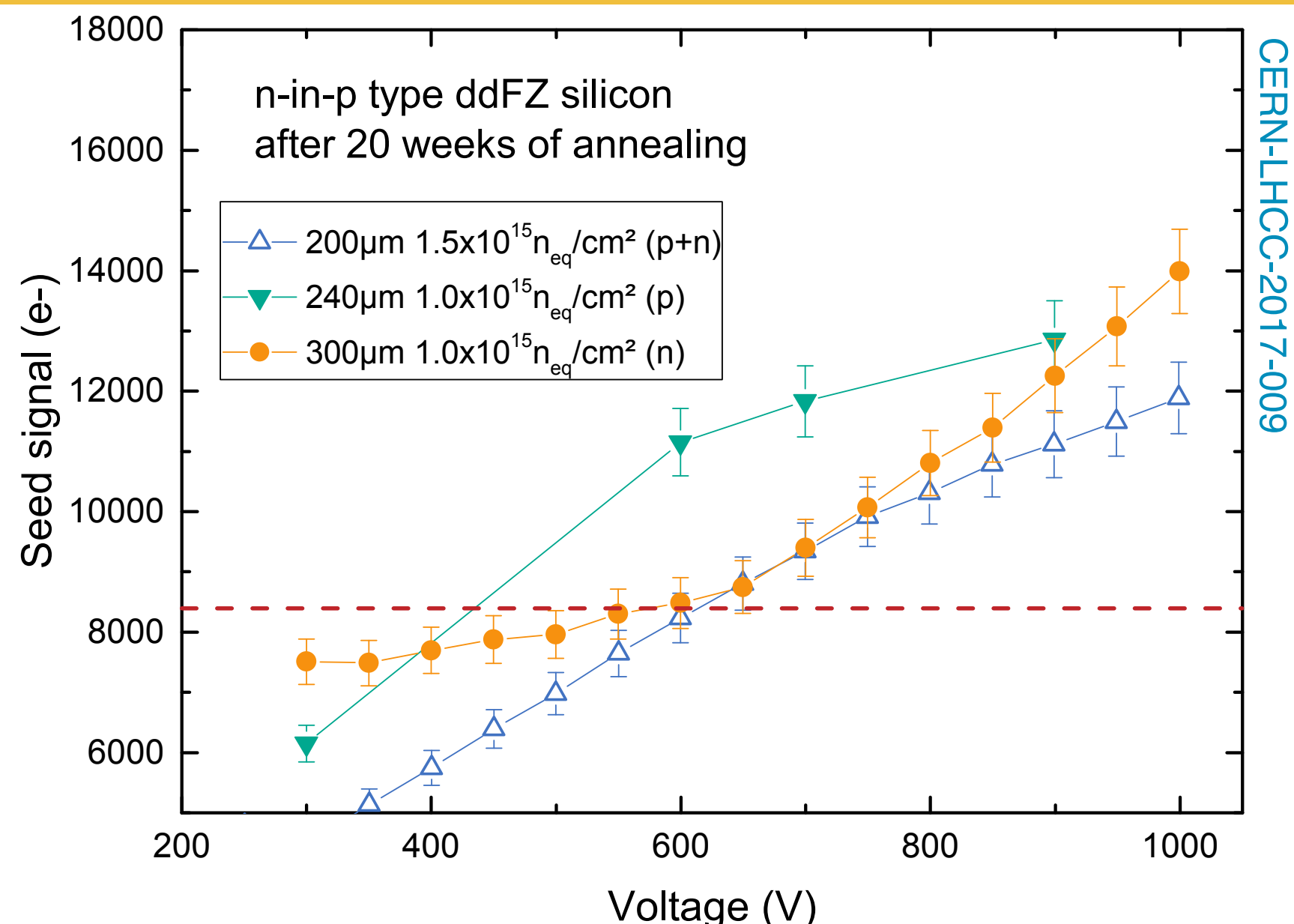




- Fast, high throughput DAQ and trigger
  - $\sim 100$ (LHC)  $\rightarrow \sim 1000$ (HL-LHC) kHz trigger accept rate
  - $\sim 4$ (LHC)  $\rightarrow \sim 10$ (HL-LHC)  $\mu\text{s}$  trigger latency to permit more complex calculations  $\Rightarrow$  deeper buffers required in front and back end electronics
  - Optical link space constraints  $\Rightarrow$  more intelligence in the front ends
- $O(50 \text{ ps})$  MIP timing resolution to discriminate interaction vertices in the same BX
- Higher channel granularity to reduce occupancy

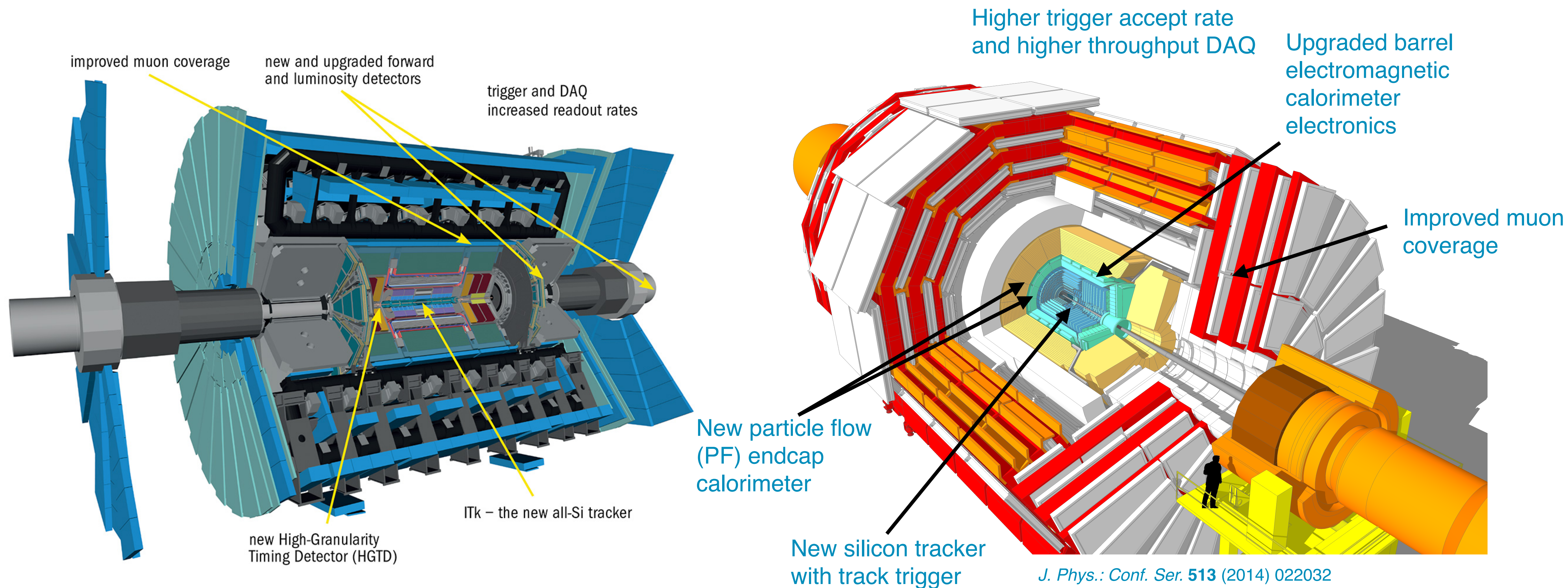
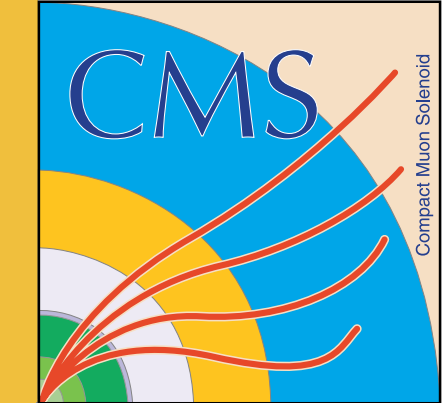


# Detector design and technology requirements



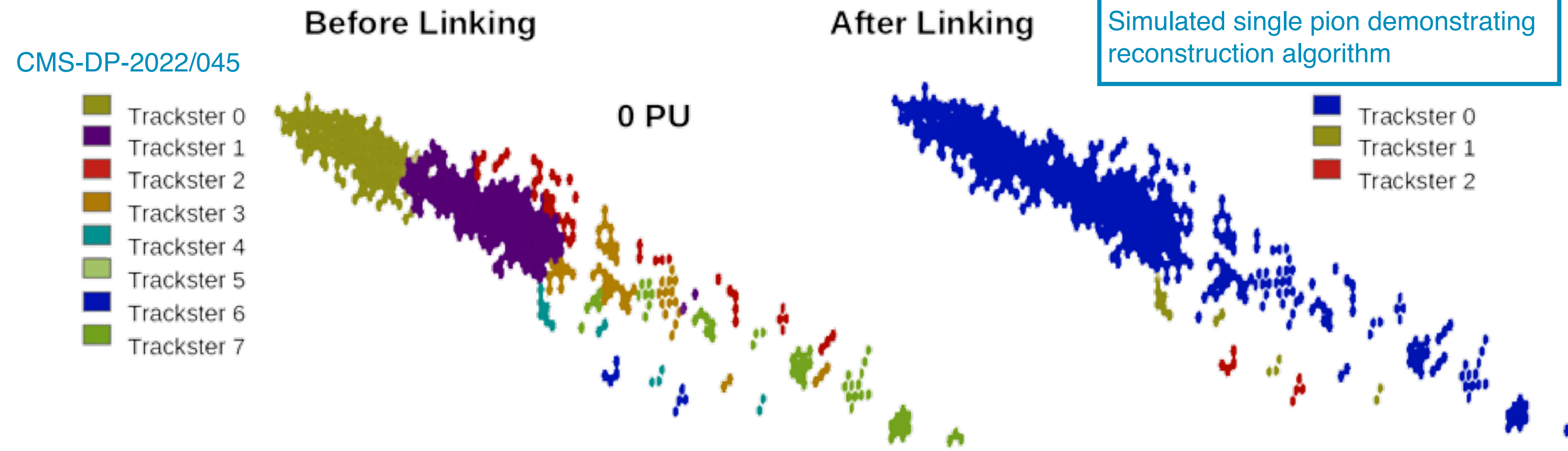
- More radiation-hard detector materials in the most critical locations: trackers, near the beam spot; and endcap calorimeter
- Thinning of silicon sensors and cooling to around  $-30^{\circ}\text{C}$  to reduce leakage current and signal loss
- Mechanics to allow for future detector replacements
- Power systems to support increased silicon bias voltage
- Maximize light yield and transparency of scintillator systems

# Highlights of the HL-LHC detector upgrades

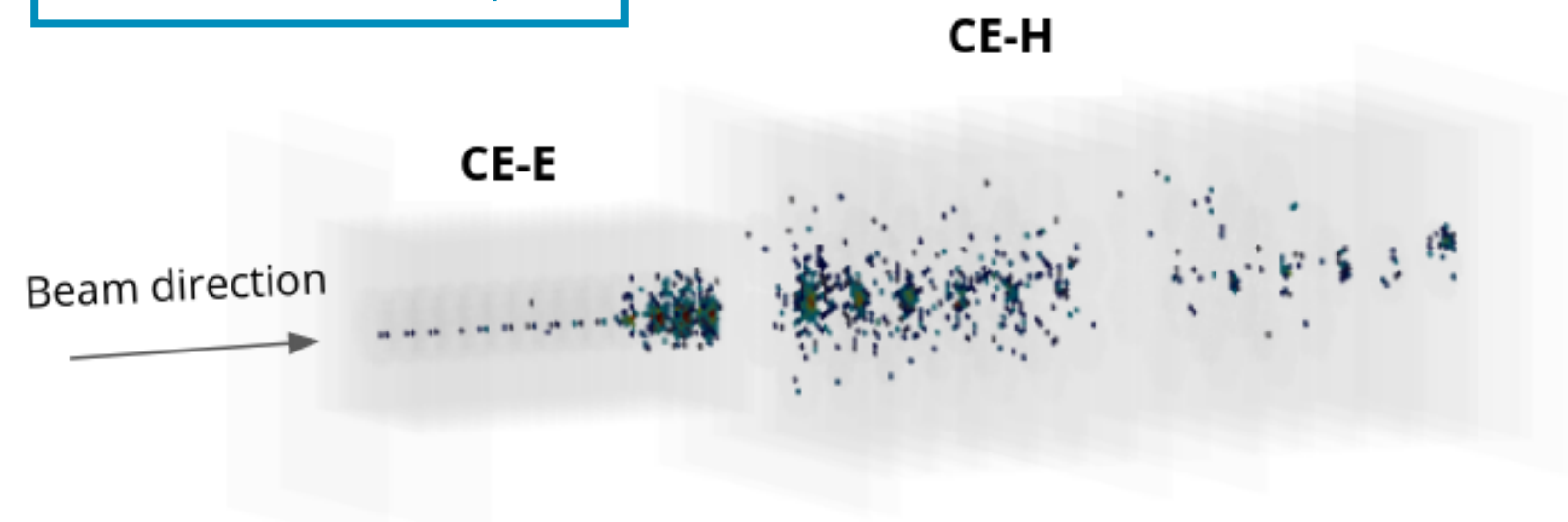


<https://cerncourier.com/a/a-new-atlas-for-the-high-luminosity-era/>

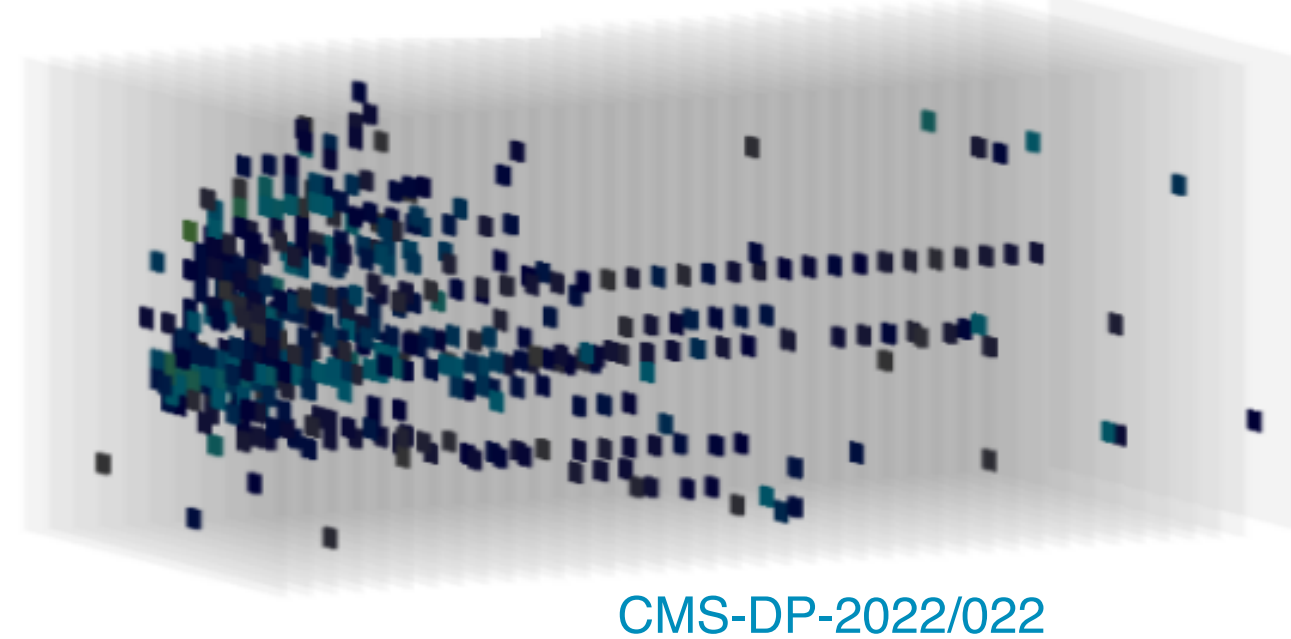
# CMS High Granularity Calorimeter (HGCAL)



Test beam 300 GeV pion



AHCAL



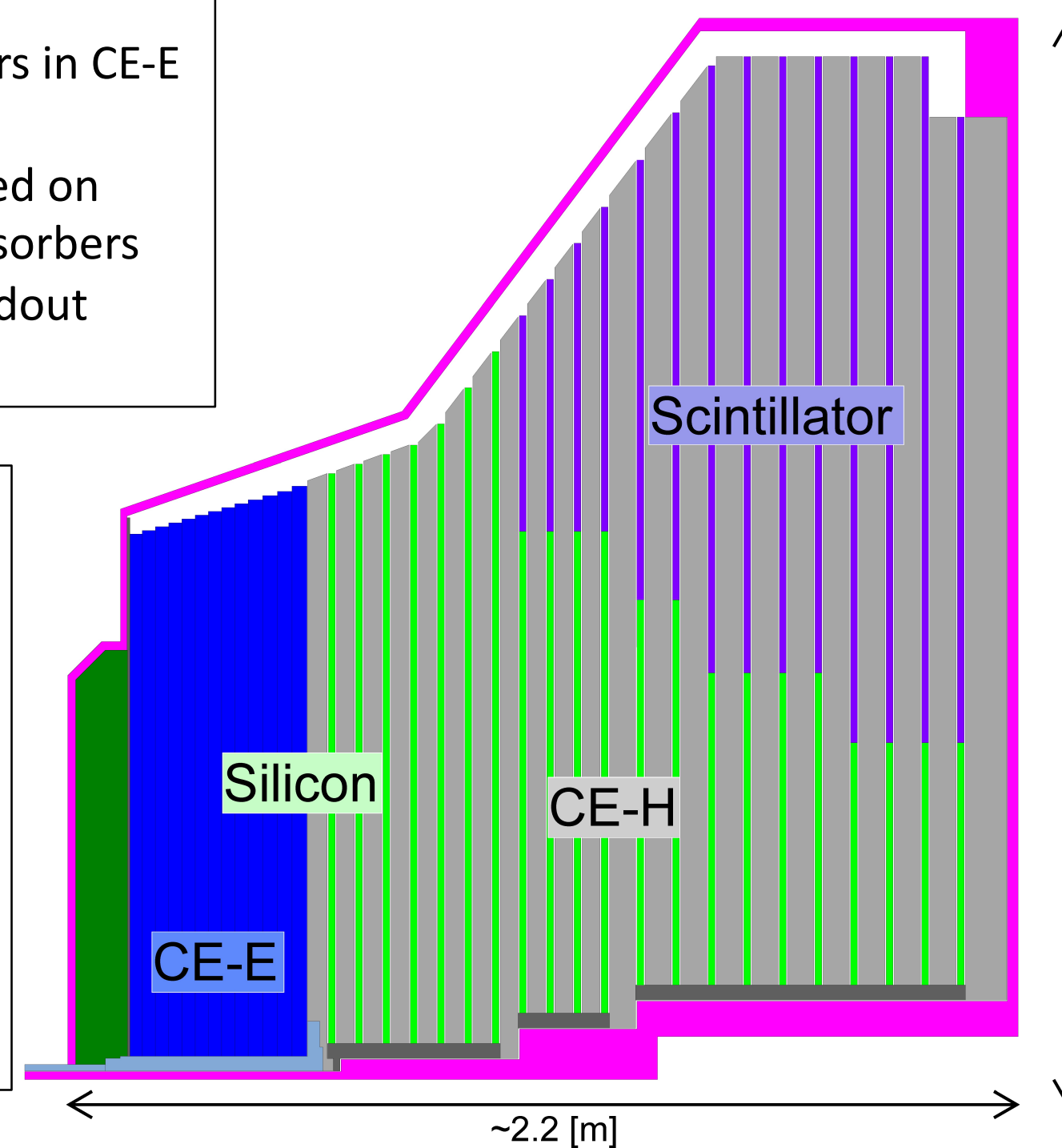
- Adapts CALICE developments for  $e^+e^-$  to use PF to reject PU and maintain good energy resolution for forward jets from vector boson scattering (VBS)
- Requires fine granularity to link the shower back to the original charged candidate of the jet

### Active Elements:

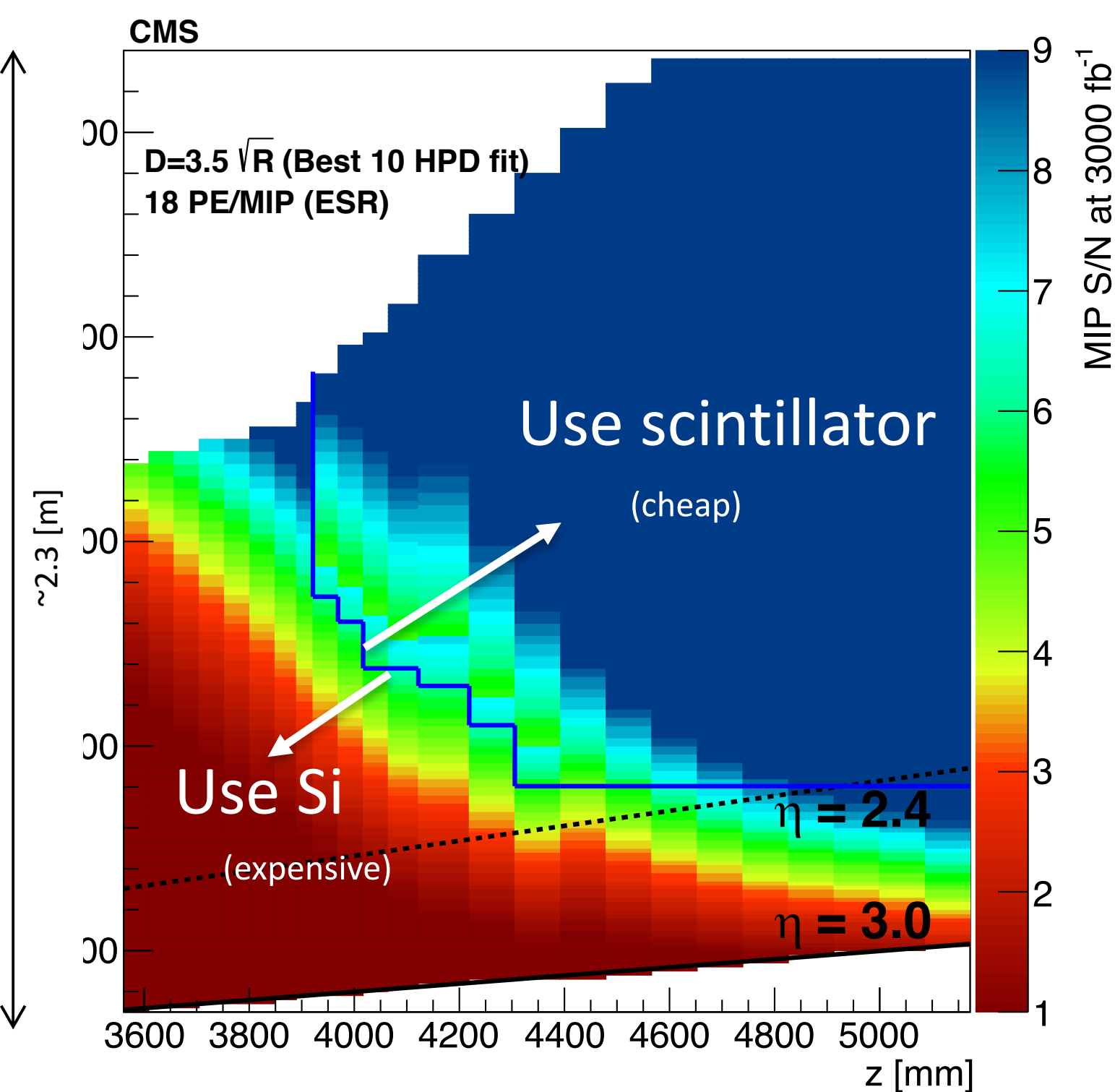
- Hexagonal modules based on Si sensors in CE-E and high-radiation regions of CE-H
- “Cassettes”: multiple modules mounted on cooling plates with electronics and absorbers
- Scintillating tiles with on-tile SiPM readout in low-radiation regions of CE-H

### Key Parameters:

Coverage:  $1.5 < |\eta| < 3.0$   
 ~215 tonnes per endcap  
 Full system maintained at  $-30^{\circ}\text{C}$   
 ~620m<sup>2</sup> Si sensors in ~26000 modules  
 ~6M Si channels, 0.6 or 1.2cm<sup>2</sup> cell size  
 ~370m<sup>2</sup> of scintillators in ~3700 boards  
 ~240k scint. channels, 4-30cm<sup>2</sup> cell size  
 Power at end of HL-LHC:  
 ~125 kW per endcap

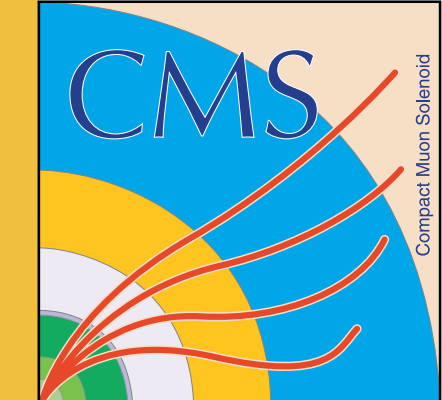


### Simulated MIP S/N after 3000 fb<sup>-1</sup> SiPM+scintillator aging



Electromagnetic calorimeter (CE-E): **Si**, Cu & CuW & Pb absorbers, 26 layers,  $27.7 X_0$  &  $\sim 1.5\lambda$   
 Hadronic calorimeter (CE-H): **Si** & **scintillator**, steel absorbers, 21 layers,  $\sim 8.5\lambda$

# CMS HGCal



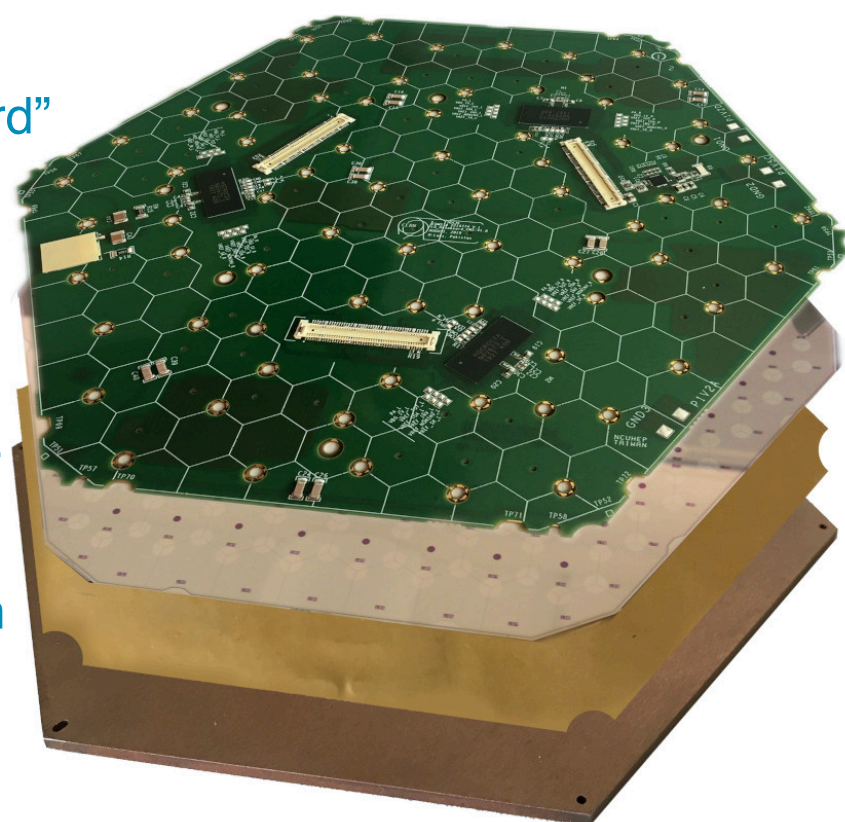
## Readout "hexaboard"

Signal digitization, trigger primitive formation  
Stepped through-holes for wirebonding

## Sensor

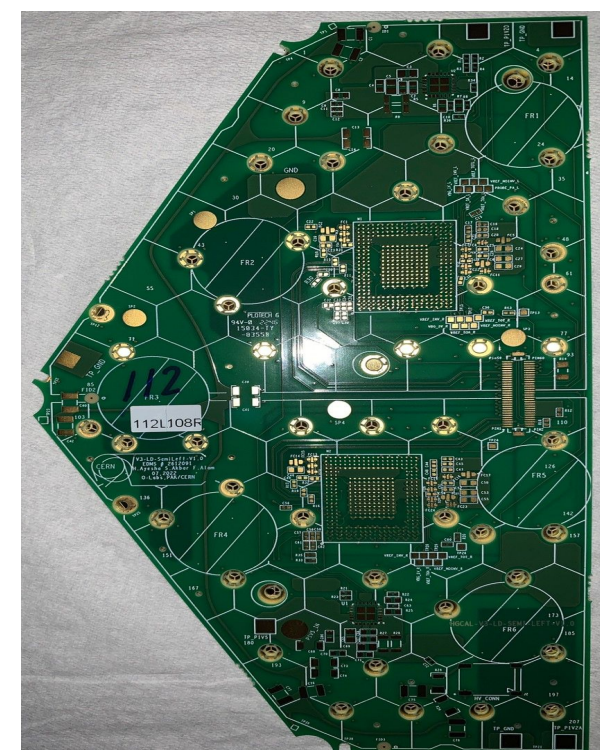
## Kapton insulation

Also carrying sensor backside bias



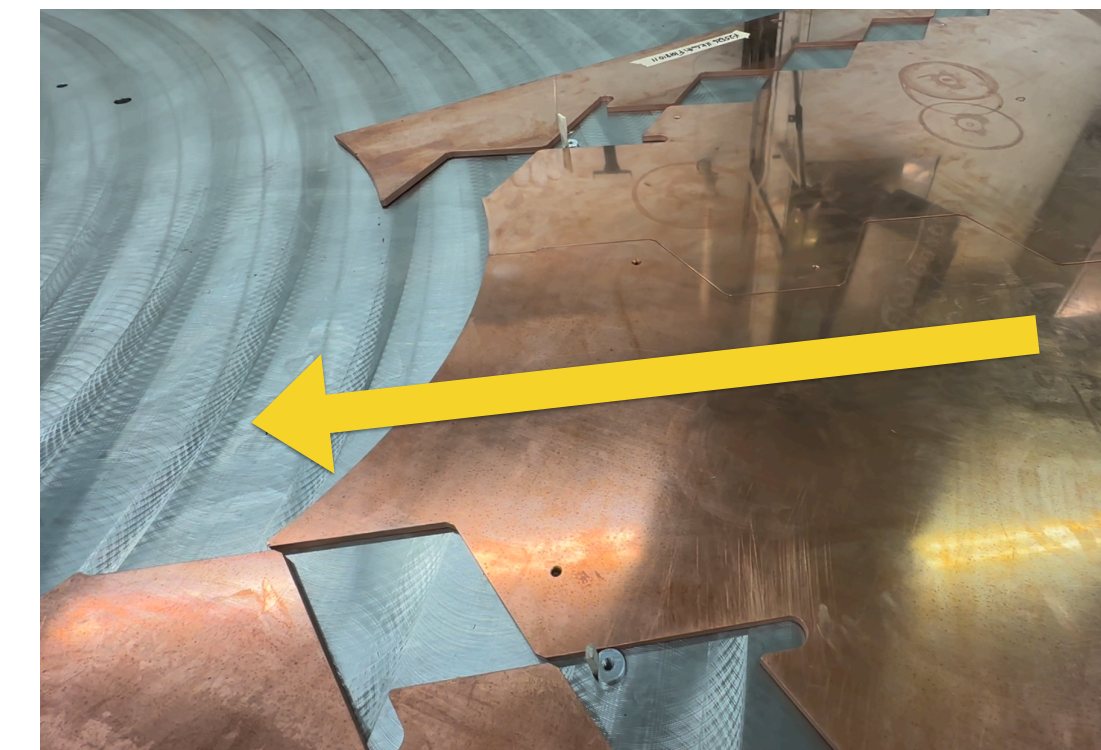
## Baseplate

Connection to cooling plate  
Part of absorber

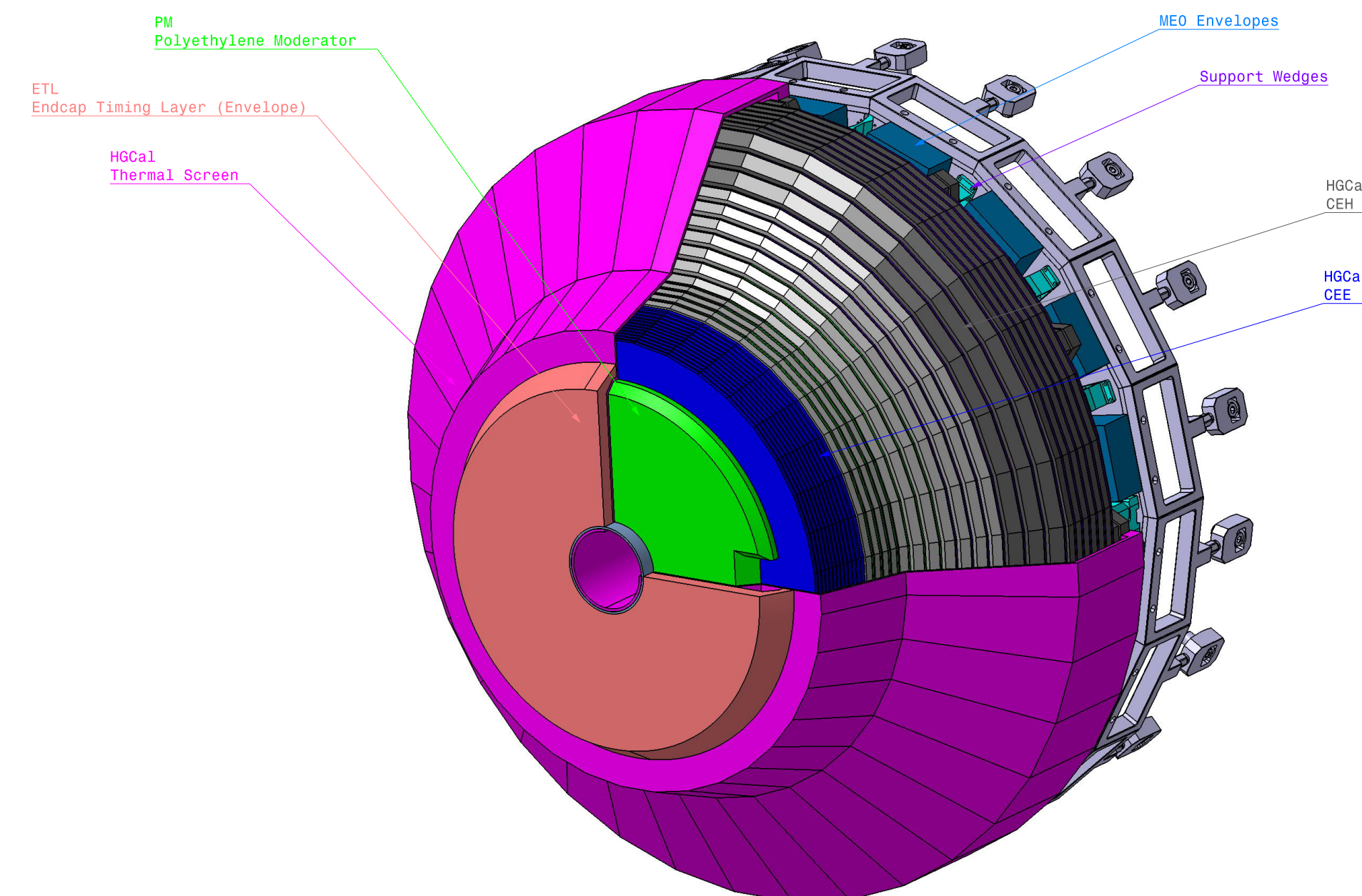


Prototype with irradiated SiPMs

## CE-H insertion test



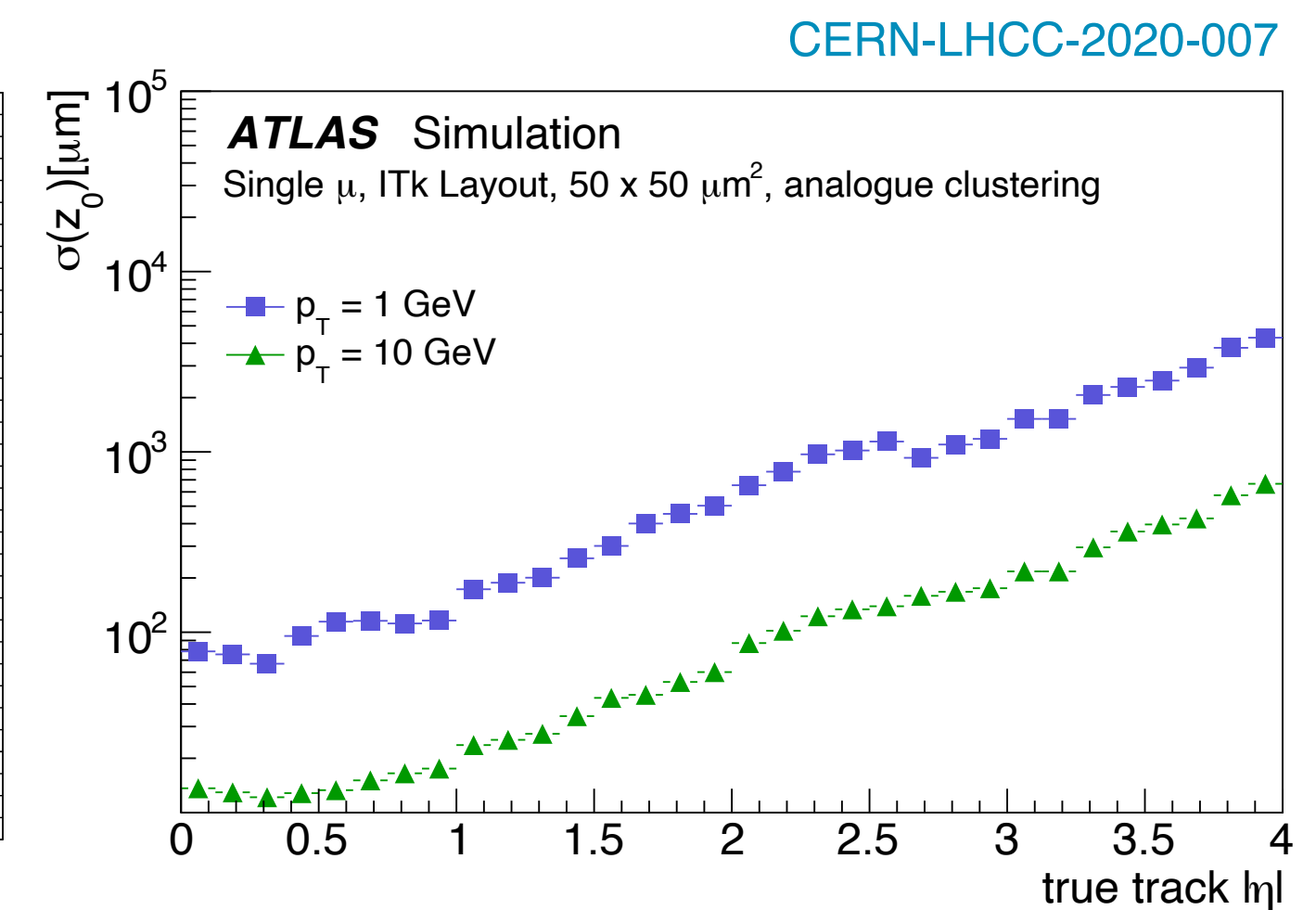
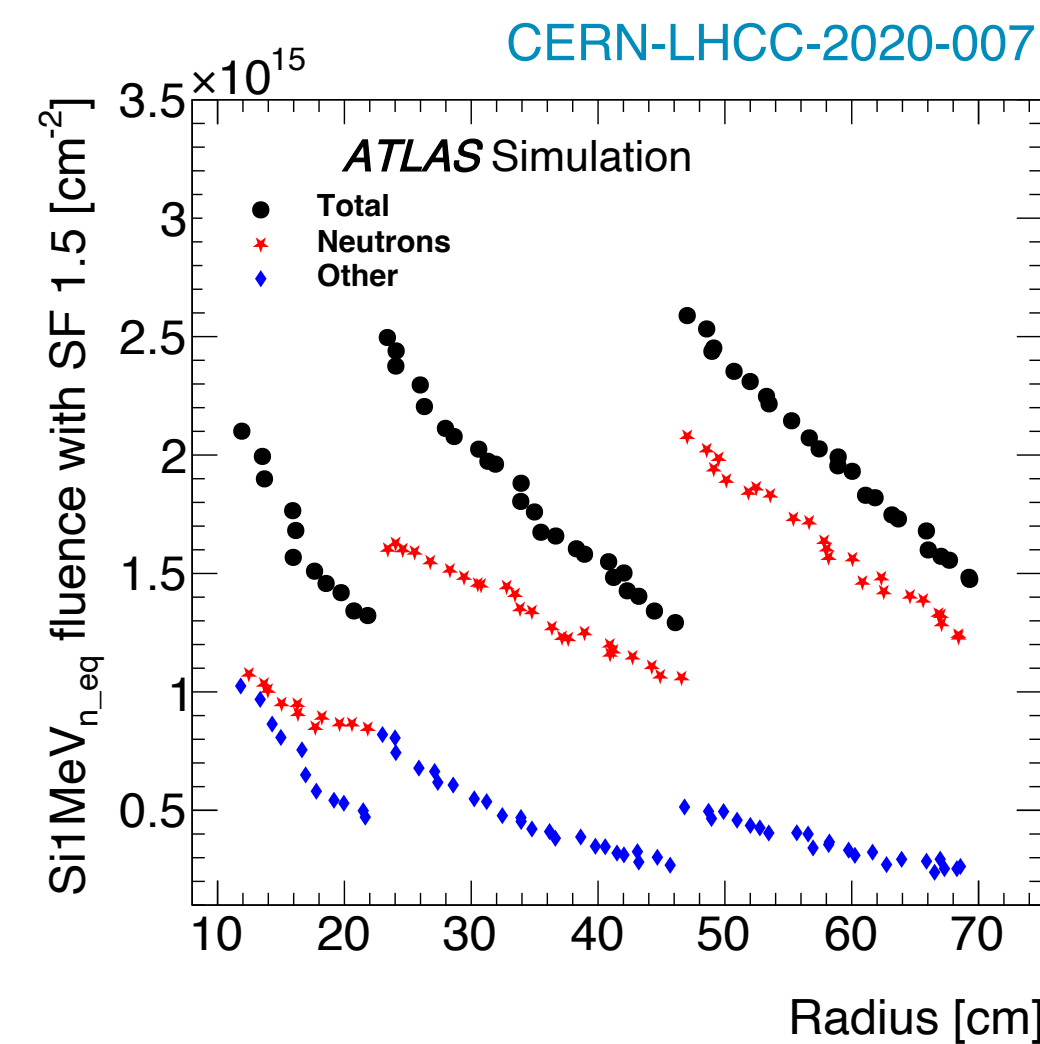
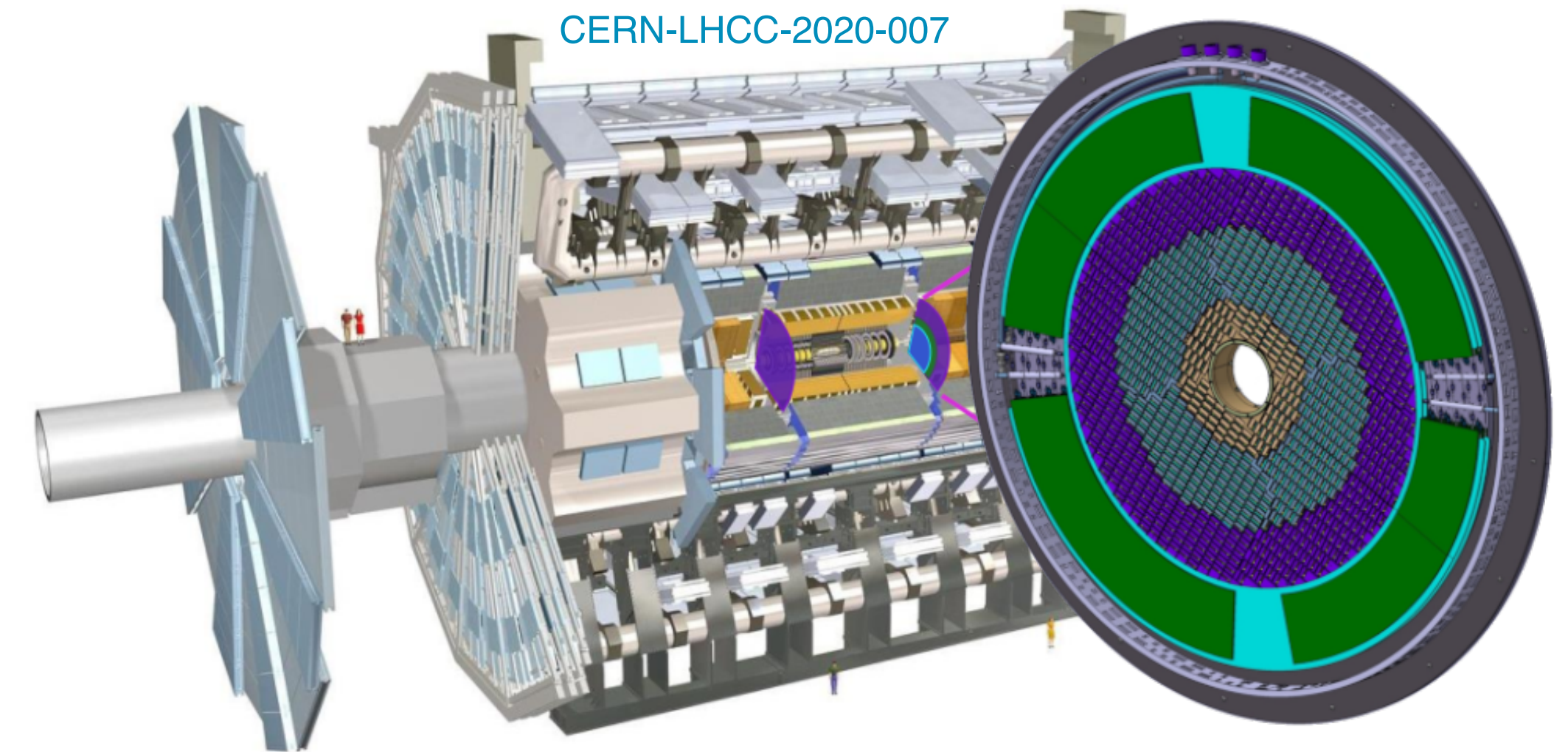
- Sensor and tile production underway
- Module production to begin late 2024



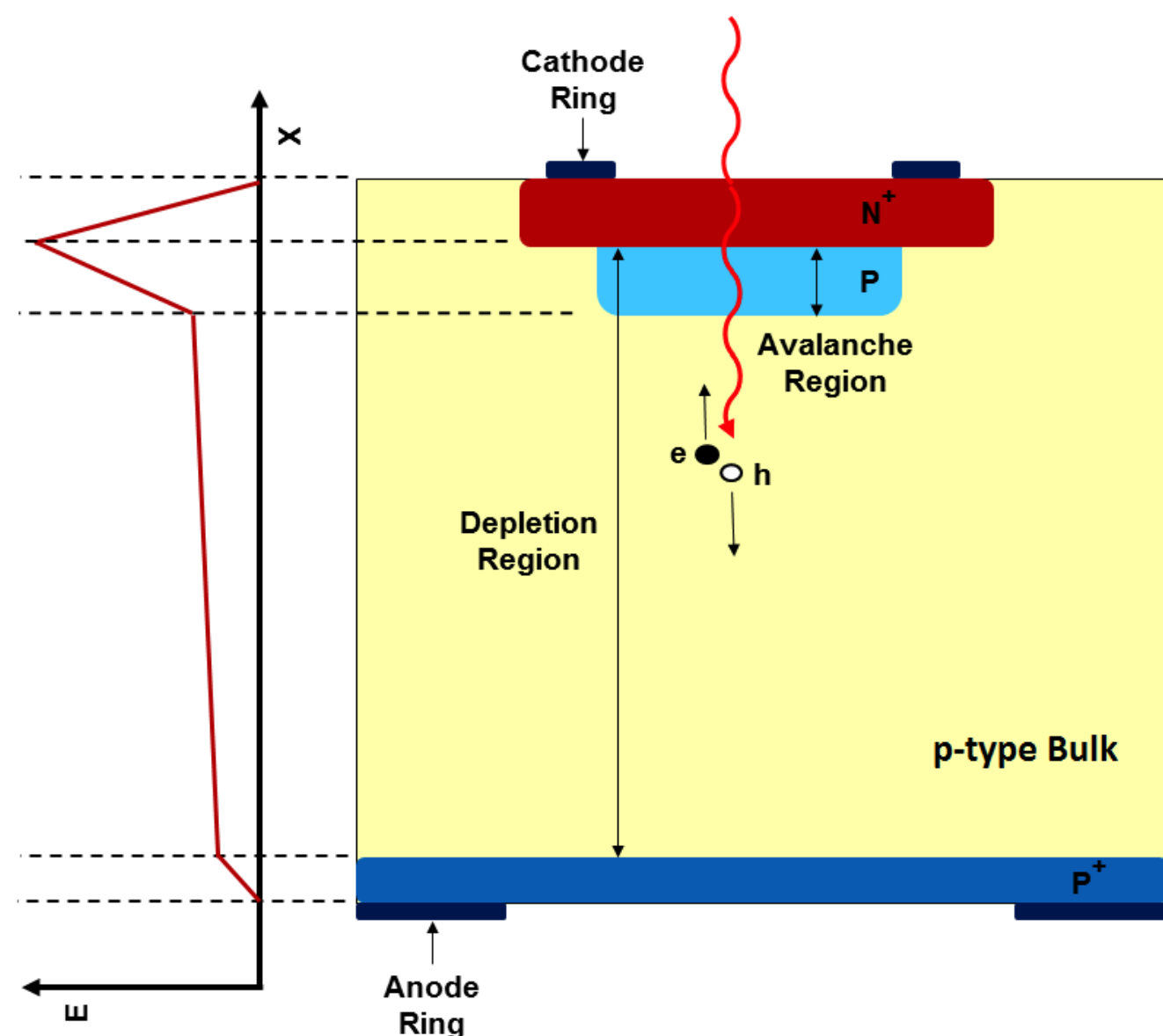
# ATLAS High Granularity Timing Detector (HGTD)



- MIP time resolution 30 (start) - 70 (end) ps
- $2.4 < |\eta| < 4.0$  to improve track z resolution in the forward region
- Doubles as a luminometer (target 1% uncertainty)
- Inner rings designed to be replaceable
- 350-550 V operating bias to achieve high S/N but avoid destructive breakdown

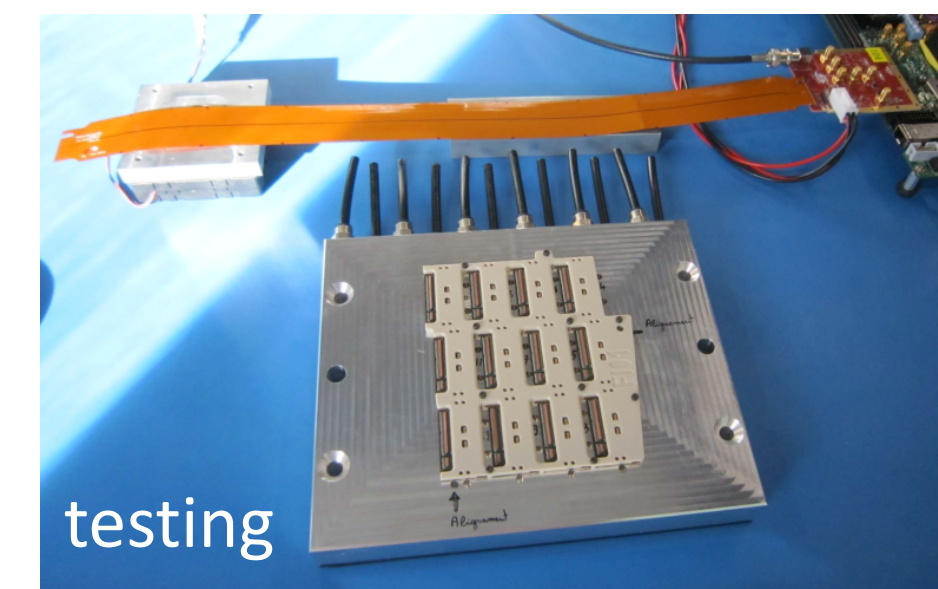
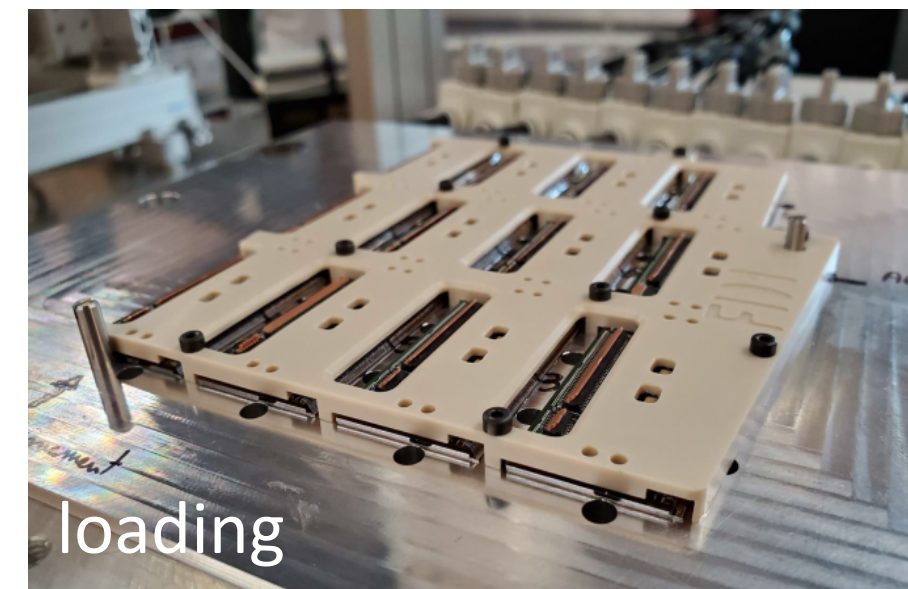
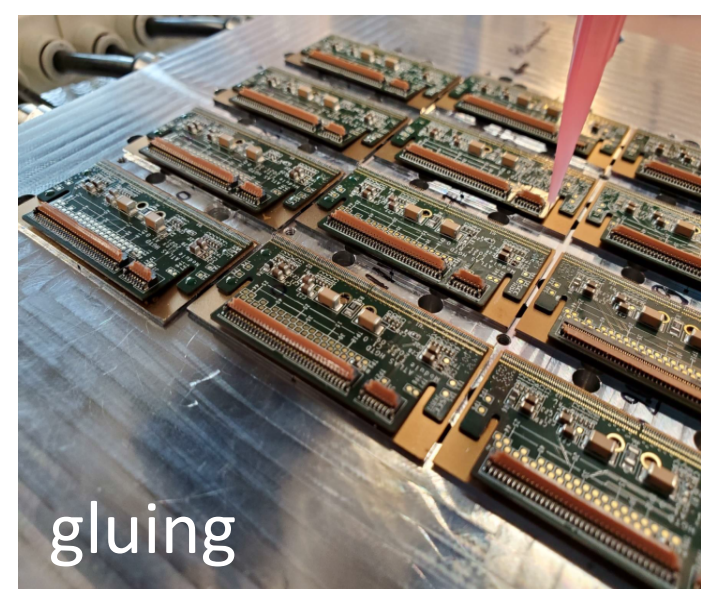
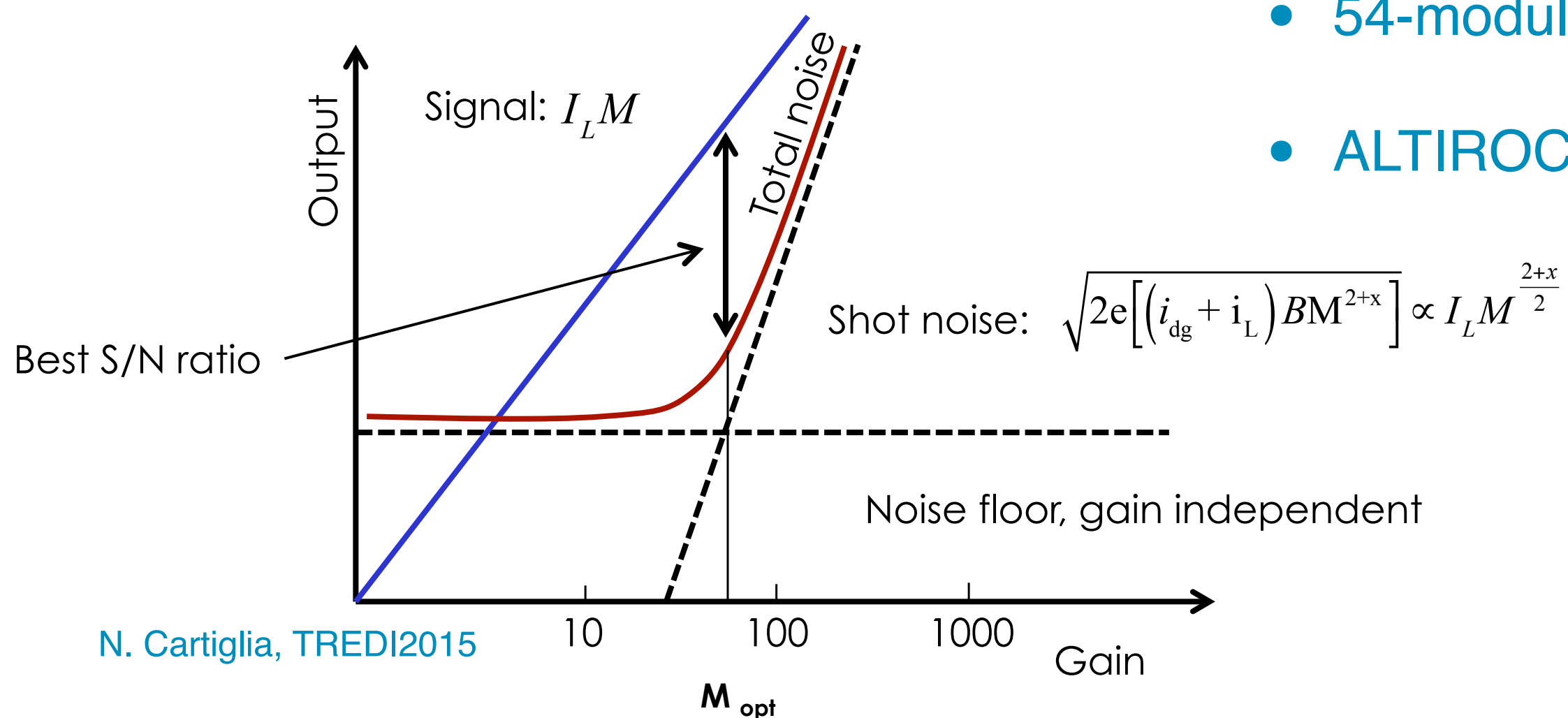


# ATLAS HGTD



CERN-LHCC-2020-007

- Low-gain avalanche detectors (LGADs)
- Reverse-biased silicon diodes with internal gain
- 50  $\mu\text{m}$  thickness with gain  $\sim 10$
- Engineered to maximize time resolution by minimizing jitter (sharp rise time from internal gain) and Landau noise (thin sensor)
- Design frozen and already in pre-production
- 54-module demonstrators under construction, first tests underway
- ALTIROC3 front end readout chip in its last prototyping round

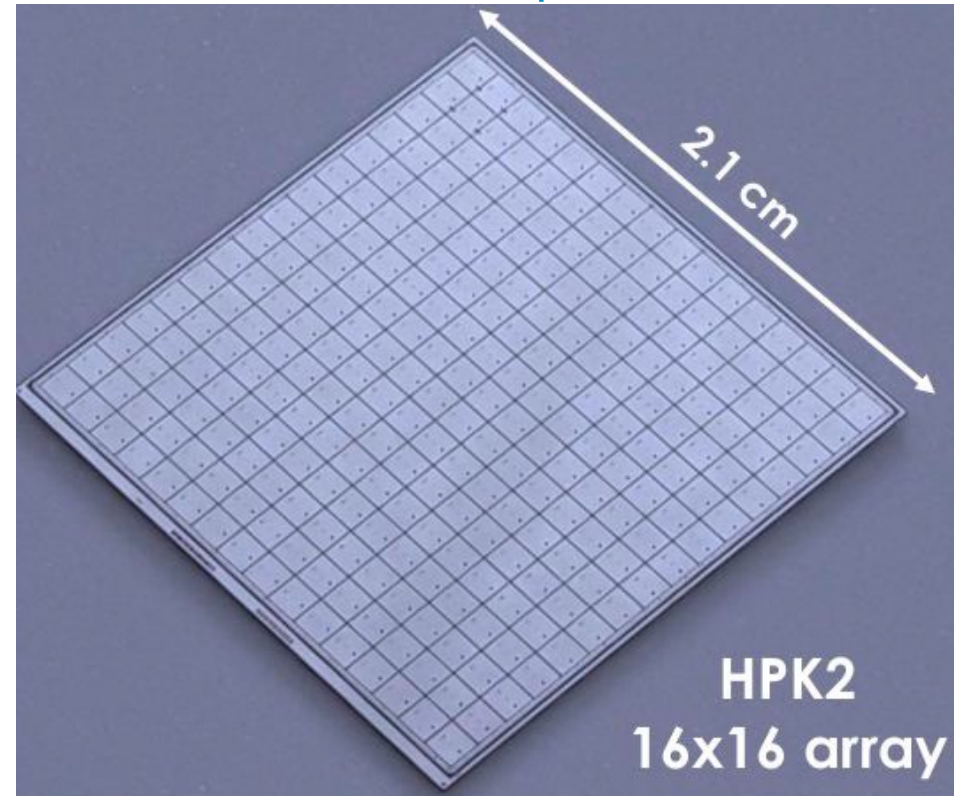


S. Terzo, VERTEX2023

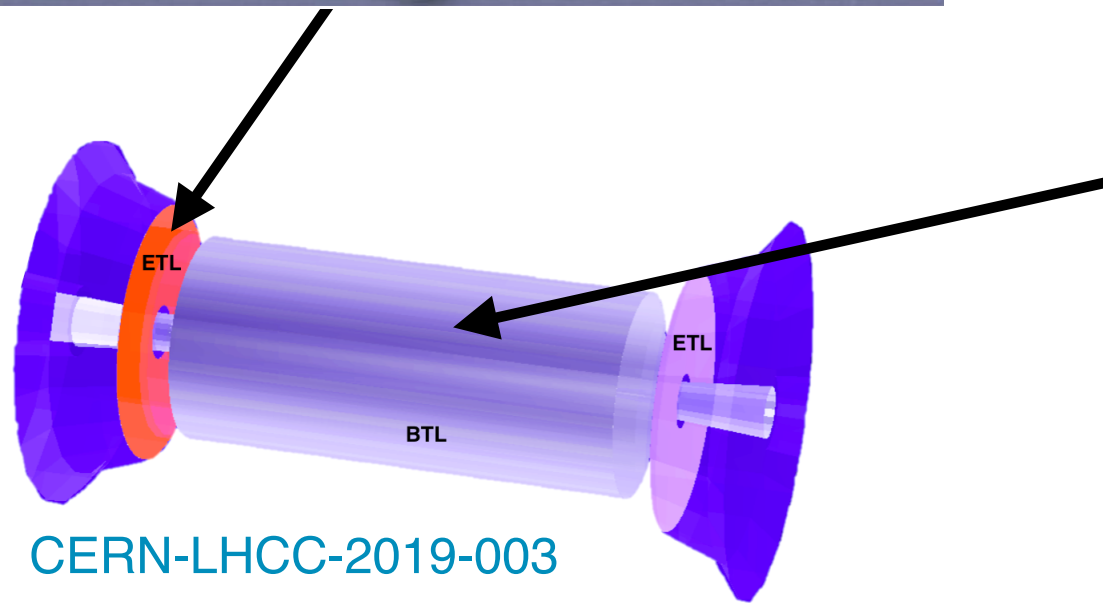
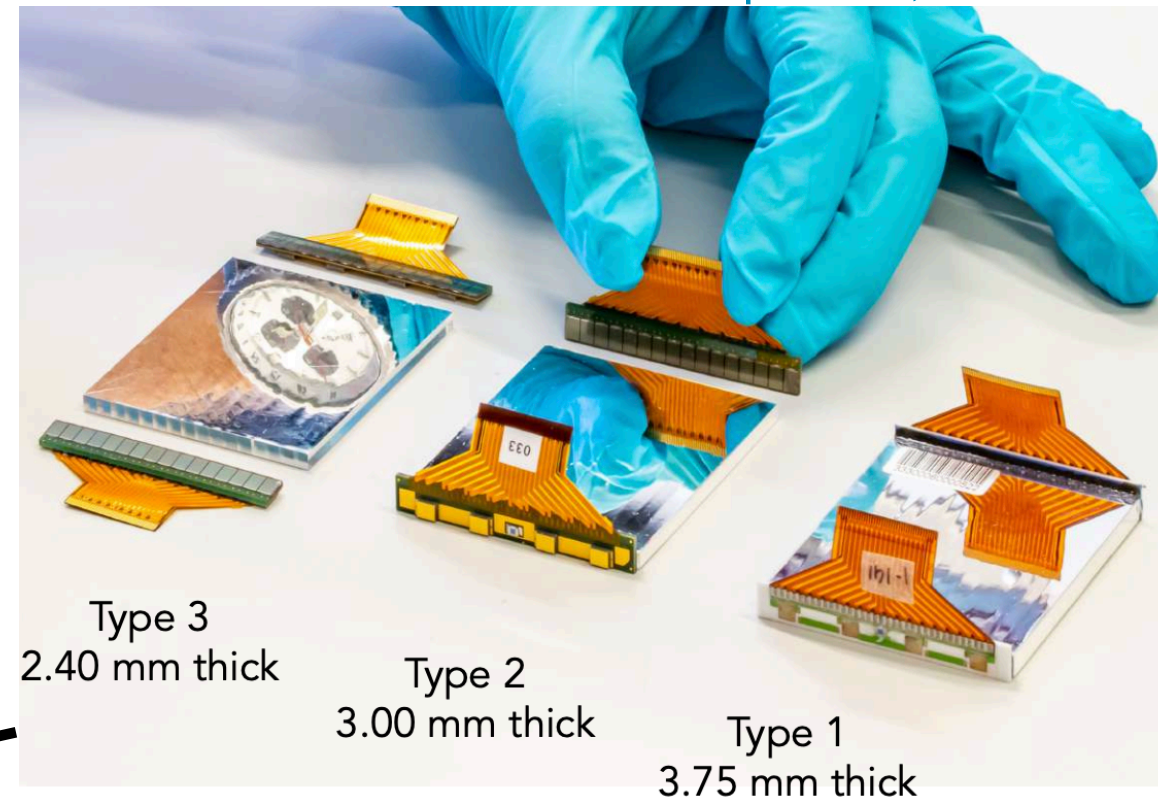
# CMS MIP Timing Detector (MTD)



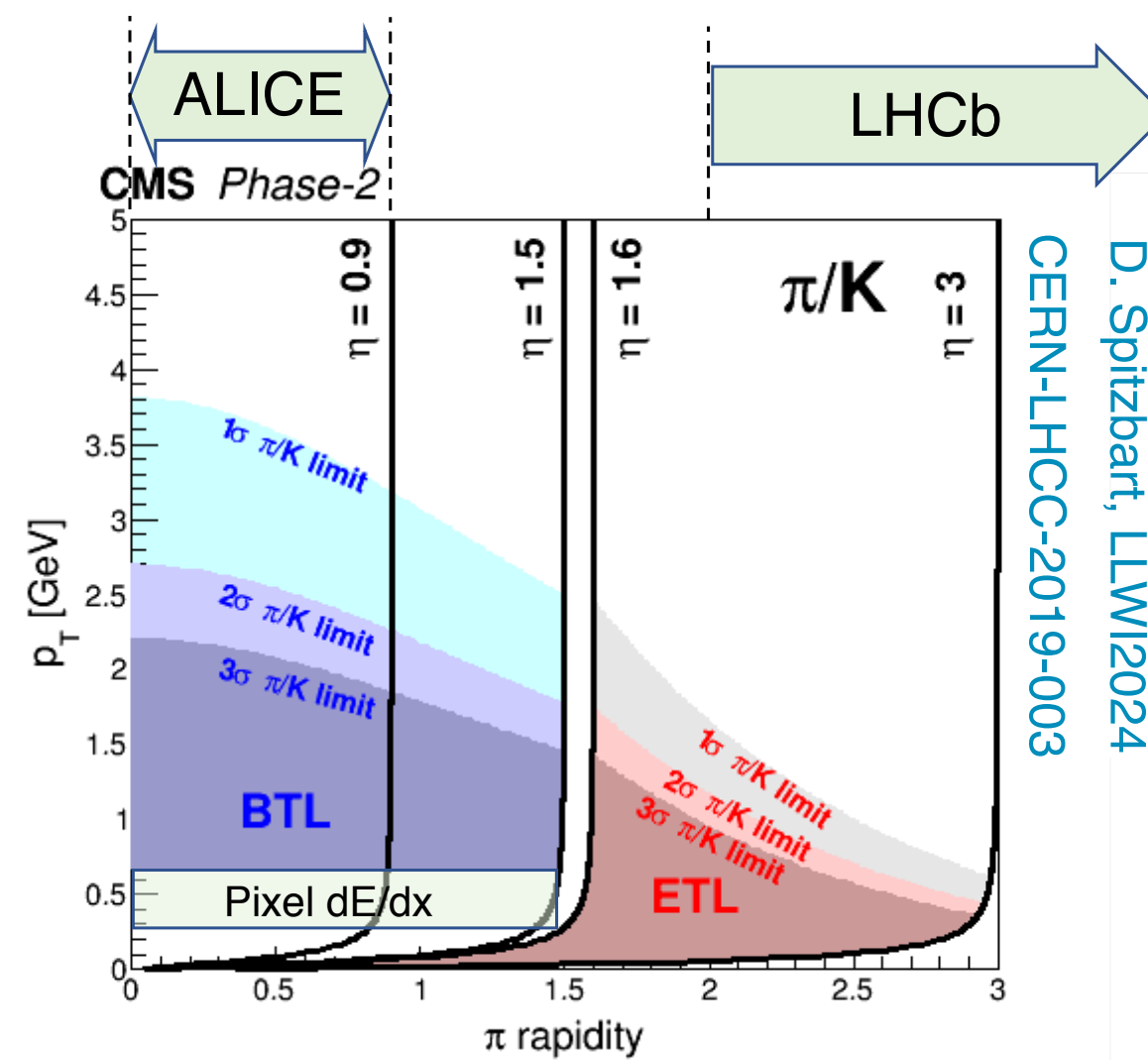
D. Spitzbart, LLWI2024



D. Spitzbart, LLWI2024



CERN-LHCC-2019-003

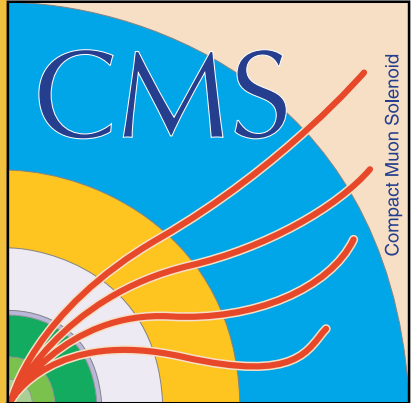


- $|\eta| < 3$ , different from ATLAS HGTD
- Motivations
  - PU rejection and its impact on vertex association and isolation in many scenarios
  - Delayed BSM, time-of-flight discrimination of exotic heavy stable charged particles (HSCPs)
  - $\pi/K$  separation for heavy ion physics

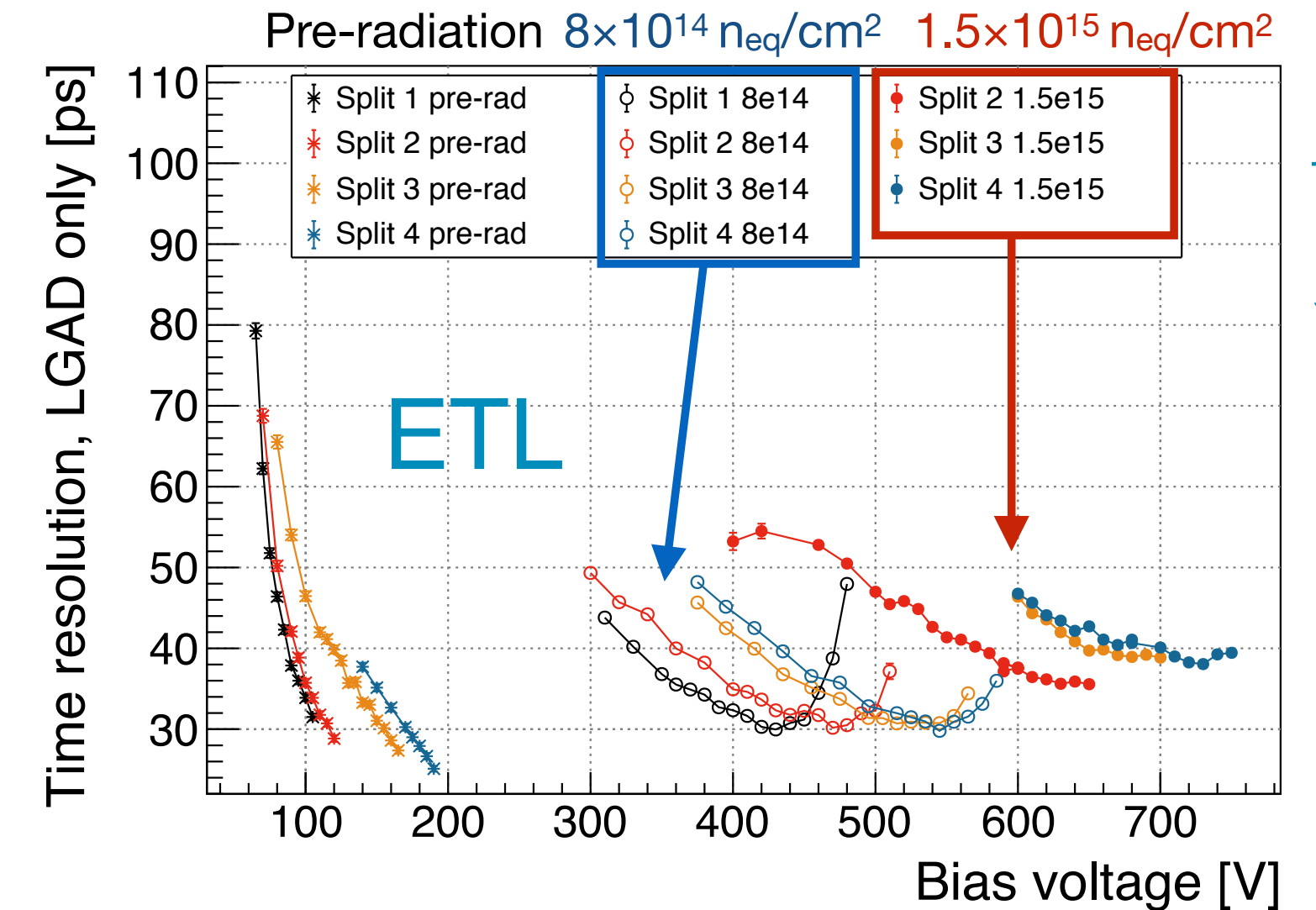
	Barrel Timing Layer (BTL)	Endcap Timing Layer (ETL)
Technology	LYSO crystal bars with SiPM readout	LGADs
$ \eta $	$< 1.45$	1.6-3.0
Surface area (m <sup>2</sup> )	$\sim 38$	$\sim 14$
No. channels	332k	$\sim 8.5M$
Fluence at 4 ab <sup>-1</sup> ( $n_{eq}/cm^2$ )	$2 \times 10^{14}$	$2 \times 10^{15}$ max



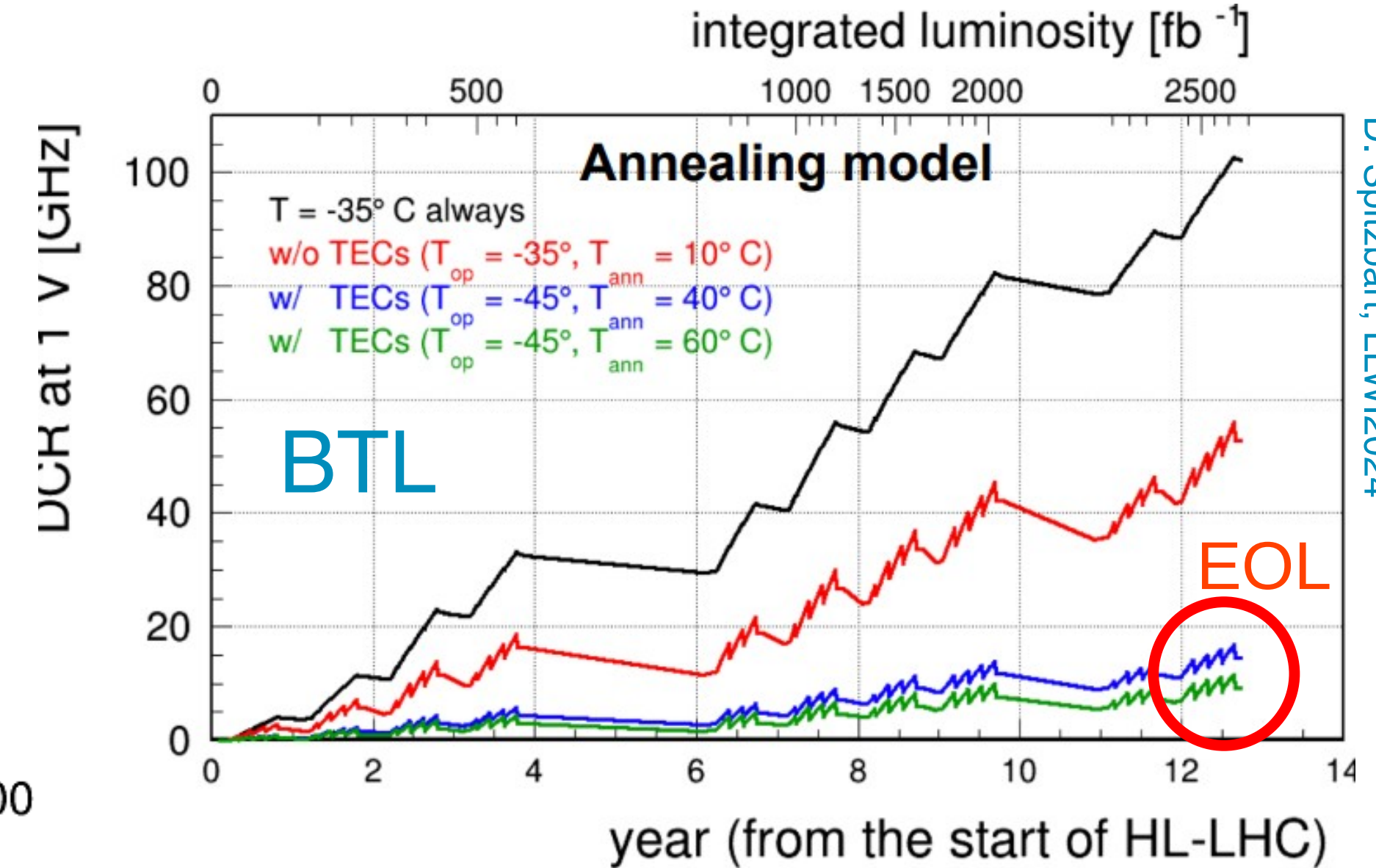
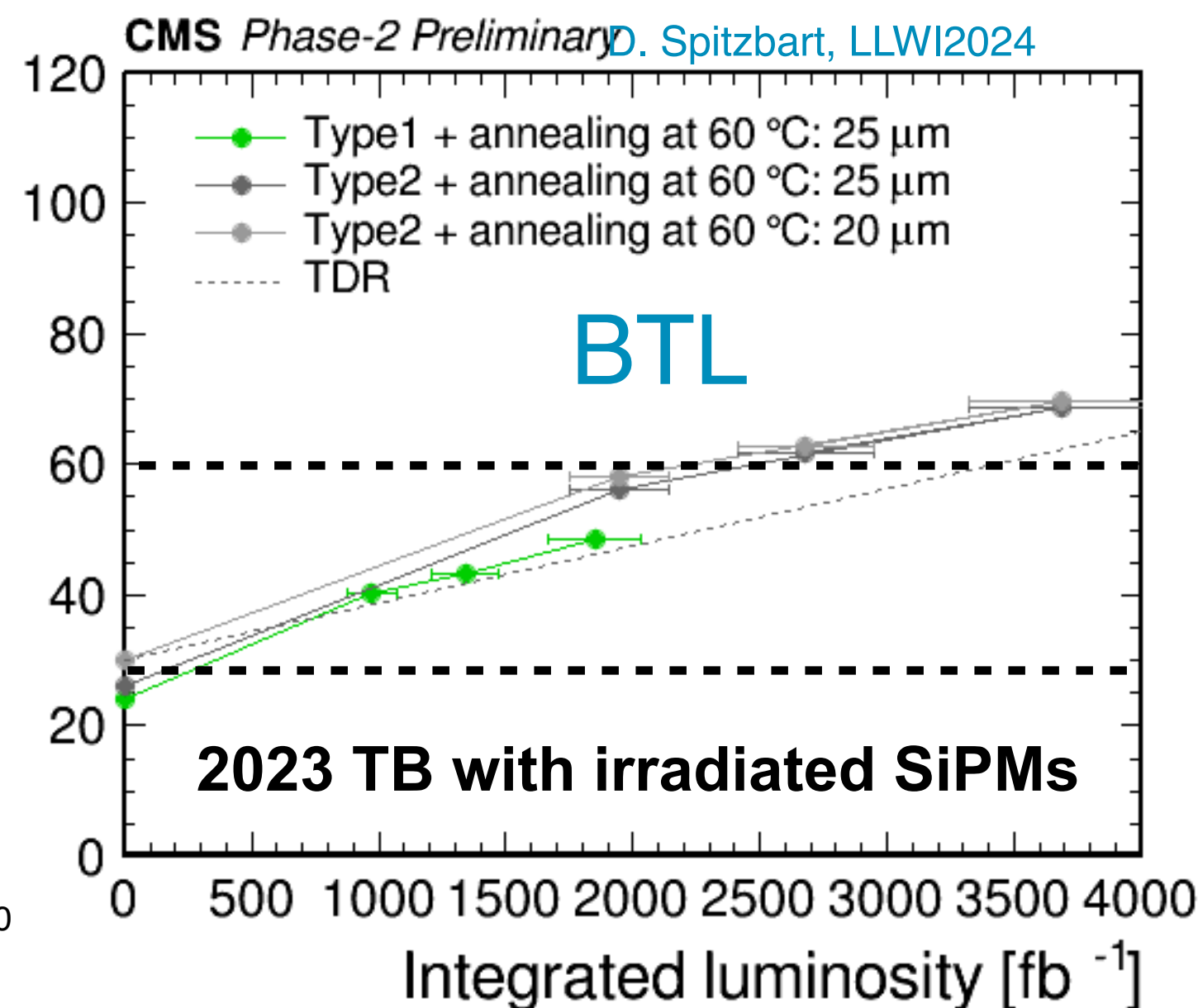
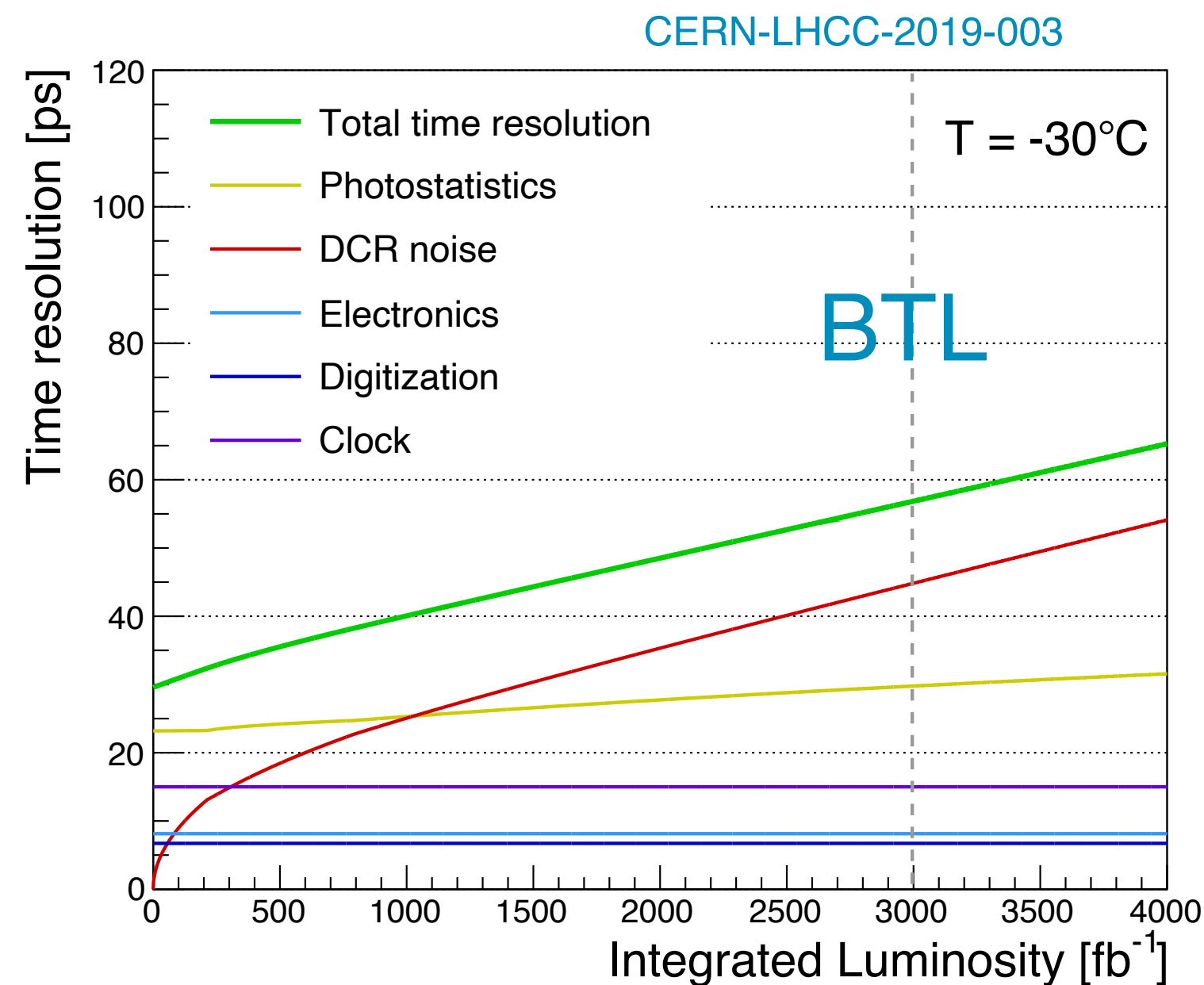
# CMS MIP Timing Detector (MTD)



- LYSO+SiPM time resolution better than 70 ps till end of life
- BTL readout chip (TOFHIR2) contribution ~13 ps
- LGAD time resolution better than 50 ps at end of life with 600 V bias (limit of safe operation)
- ETL readout chip (ETROC) contribution < 40 ps



D. Spitzbart, LLWI2024

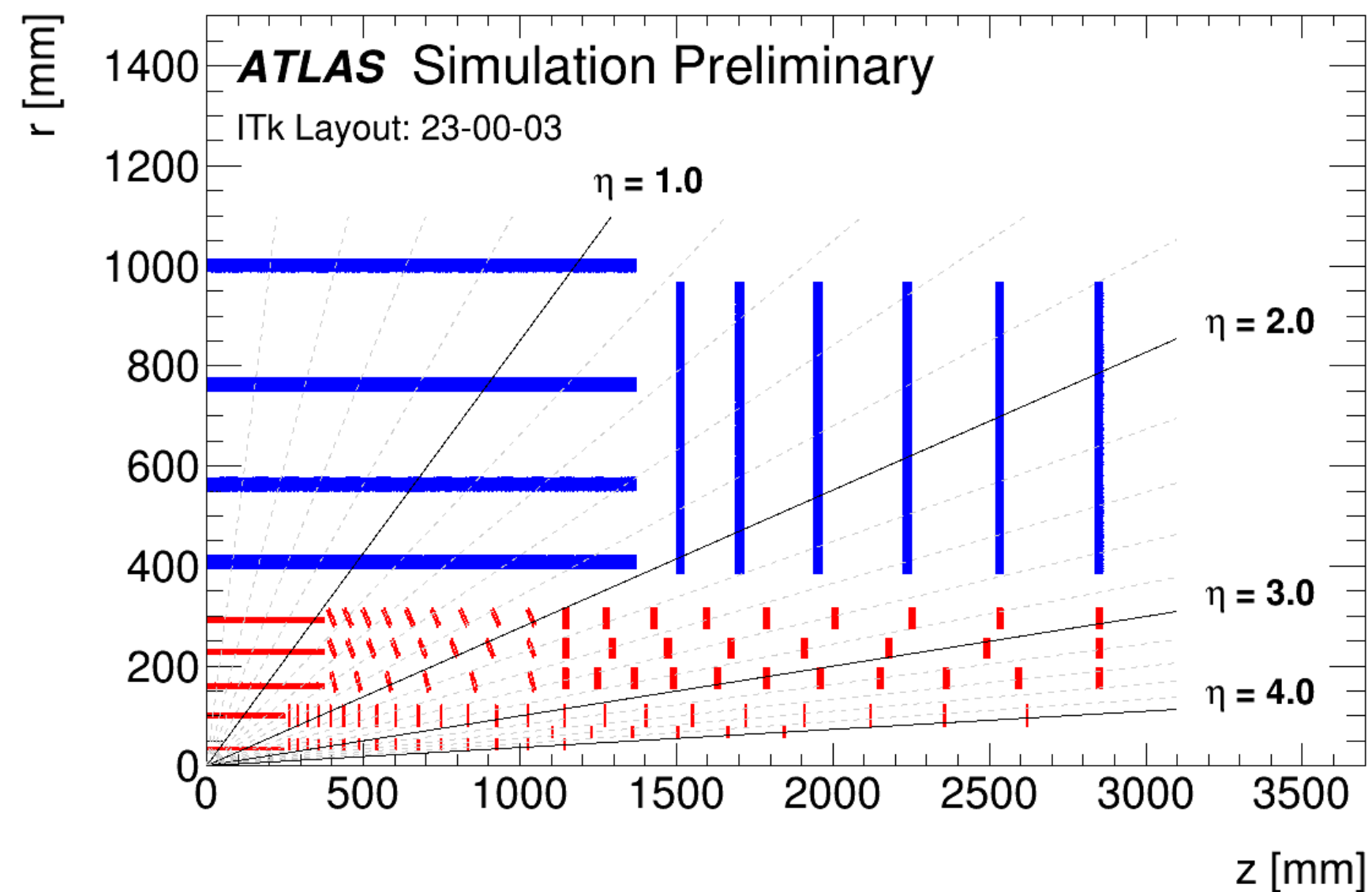


D. Spitzbart, LLWI2024

# ATLAS Inner Tracker (ITk)

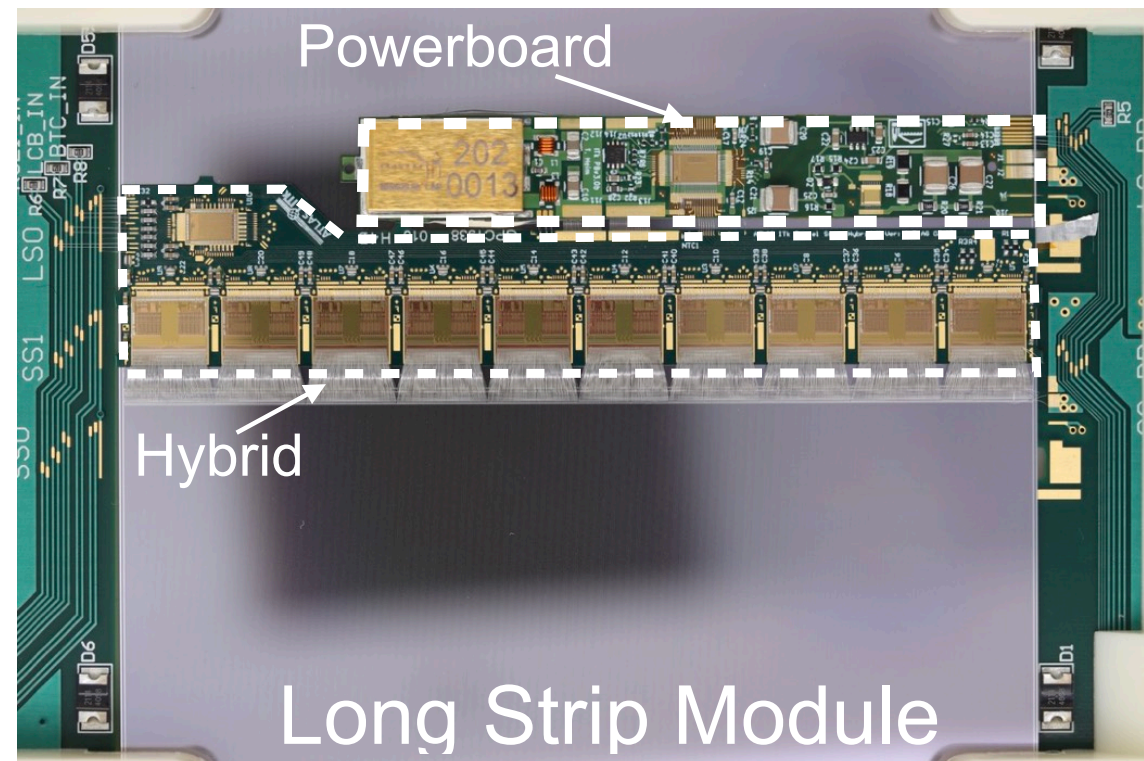
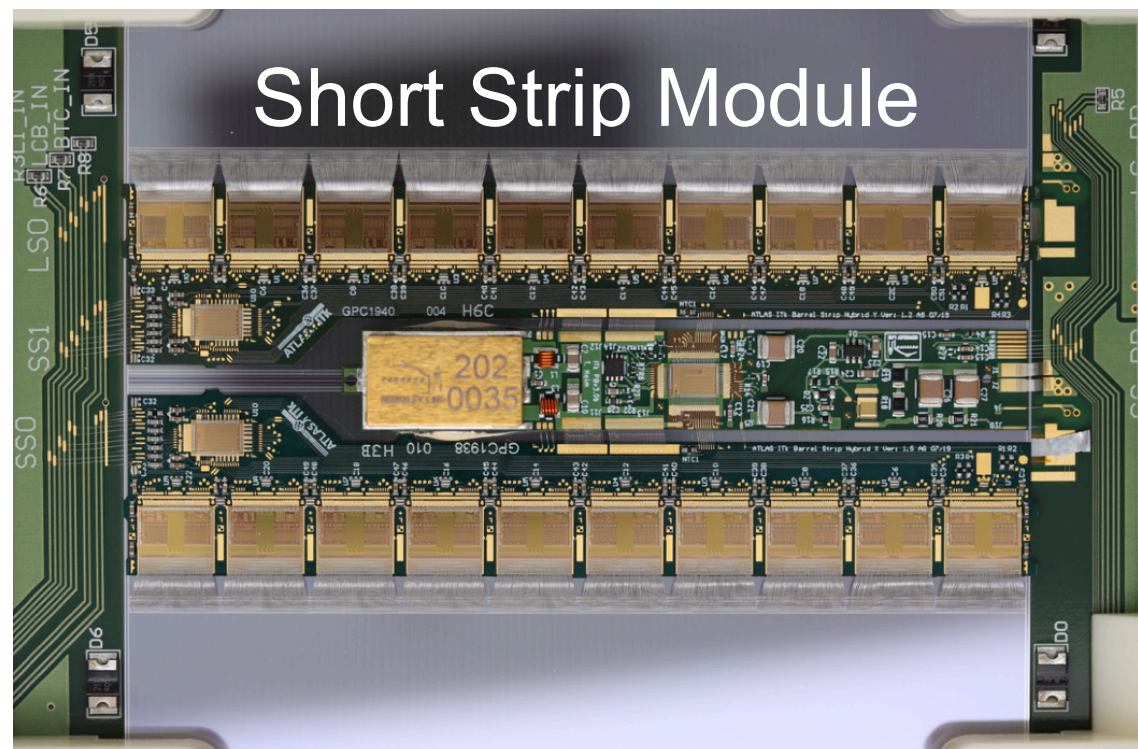


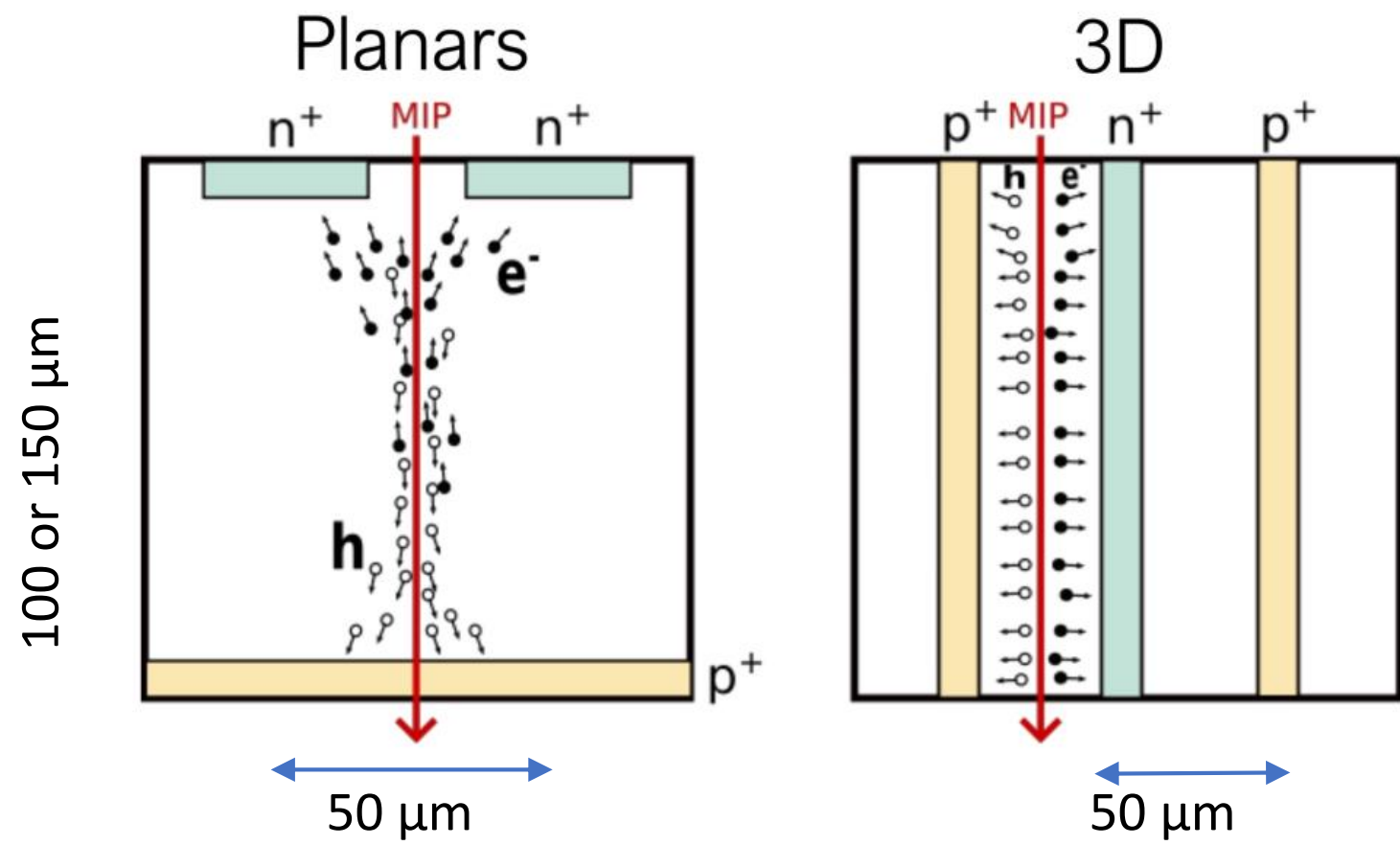
ATLAS-PHYS-PUB-2021-024



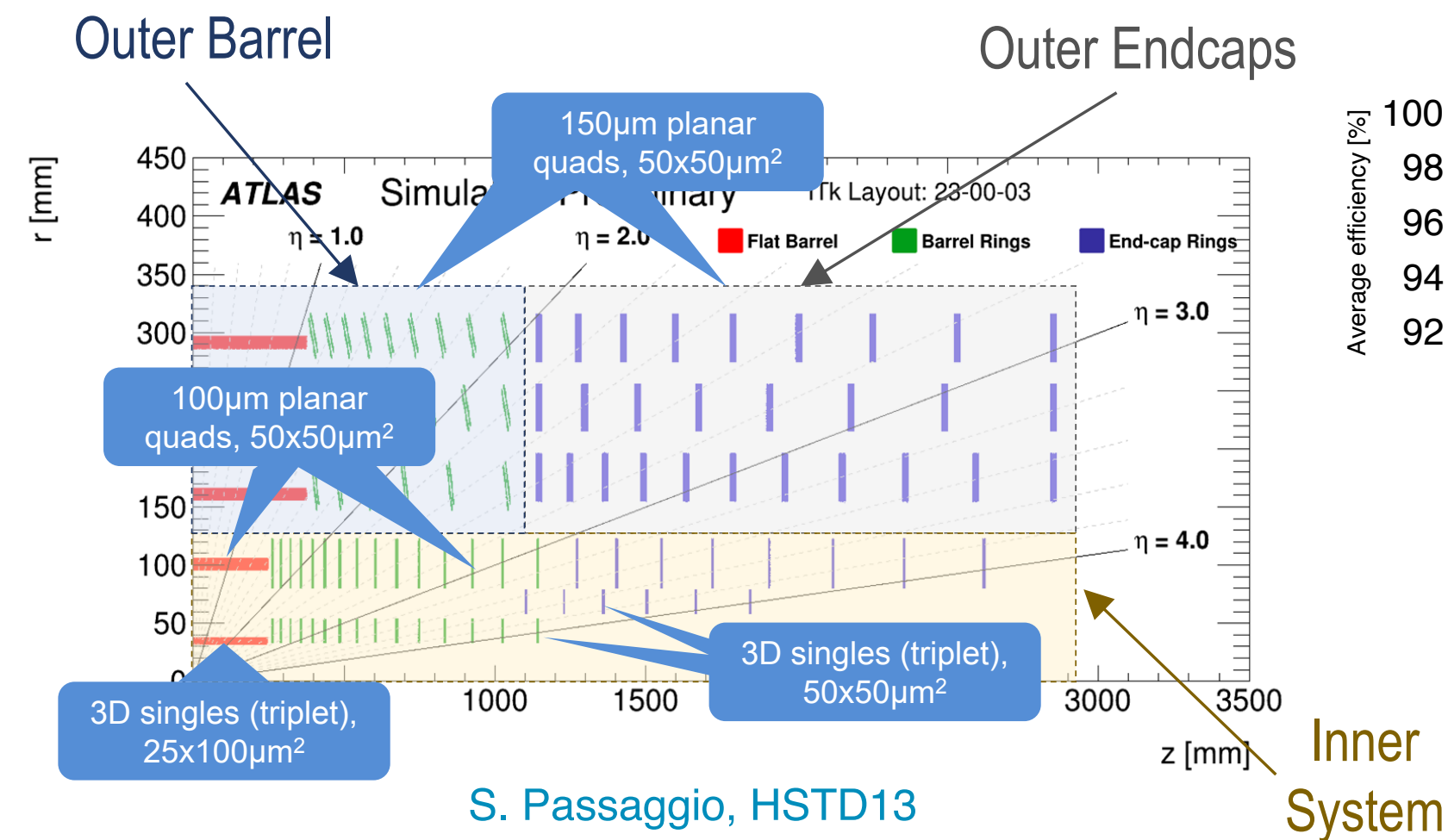
- Mixed silicon/transition-radiation tracker replaced with all-silicon tracker
- $|\eta| < 4$ , same as CMS, with at least 9 hits per track to facilitate VBS jet identification
- Tilt of some endcap pixel sensors to improve track finding and reduce multiple scattering
- Layers 0 and 1 to be replaced after 2000  $\text{fb}^{-1}$ ; layers 3-5 survive to 4000  $\text{fb}^{-1}$
- $\text{CO}_2$  cooling, serial powering in pixel detector, and carbon fiber structures to minimize mass

G. Iakovidis, HSTD13

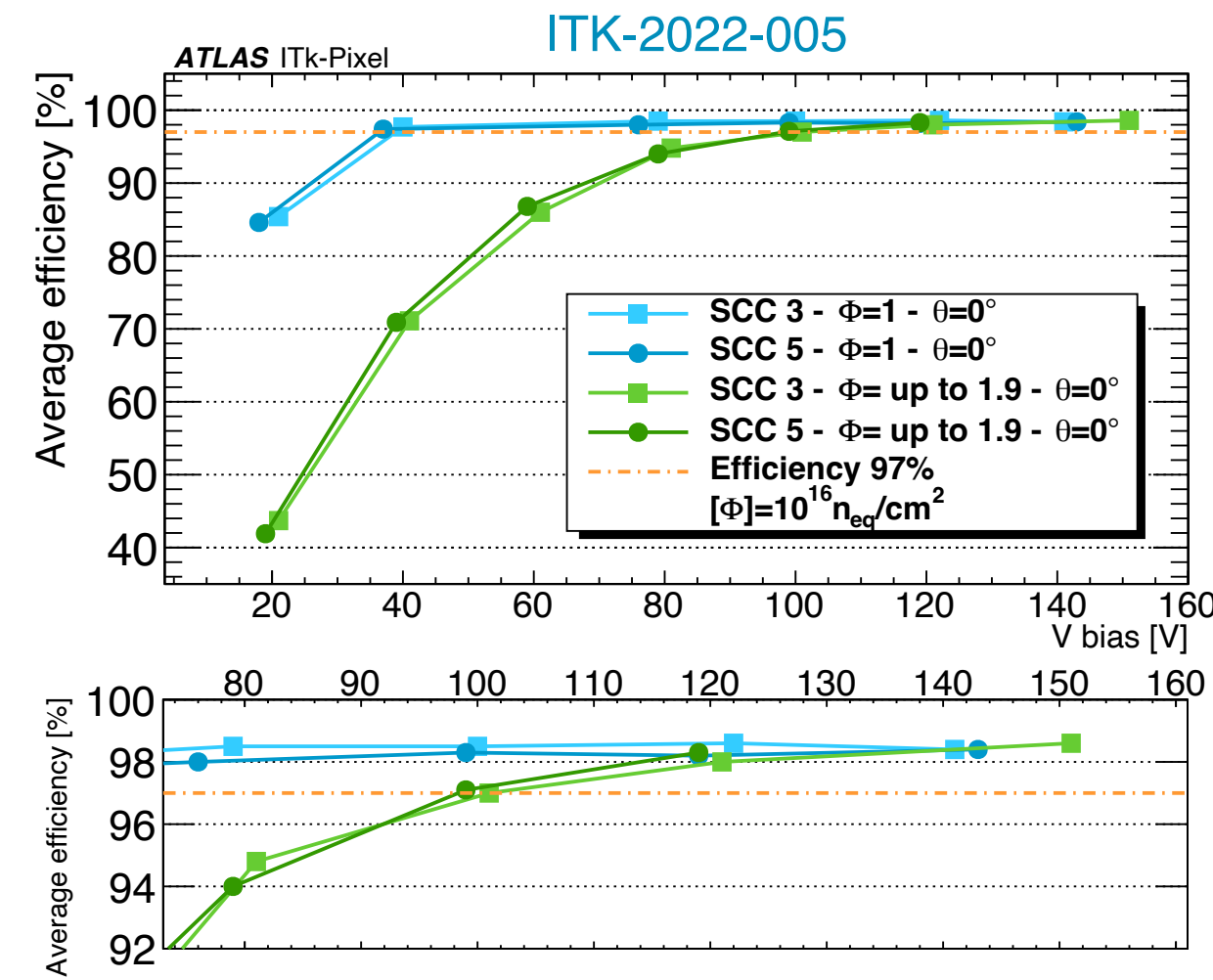




S. Passaggio, HSTD13



S. Passaggio, HSTD13

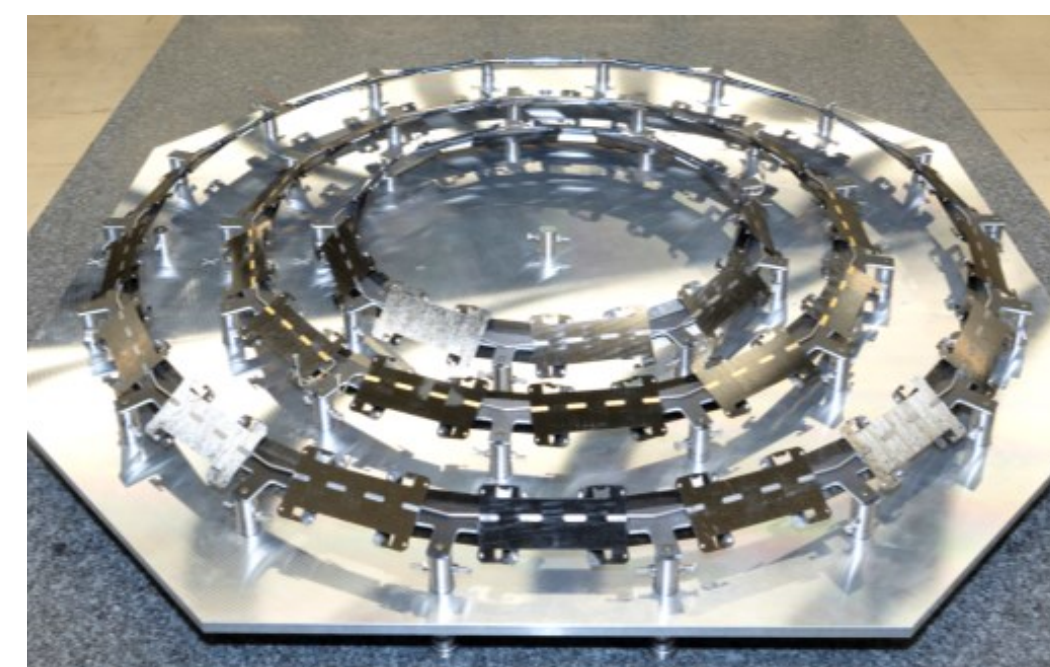
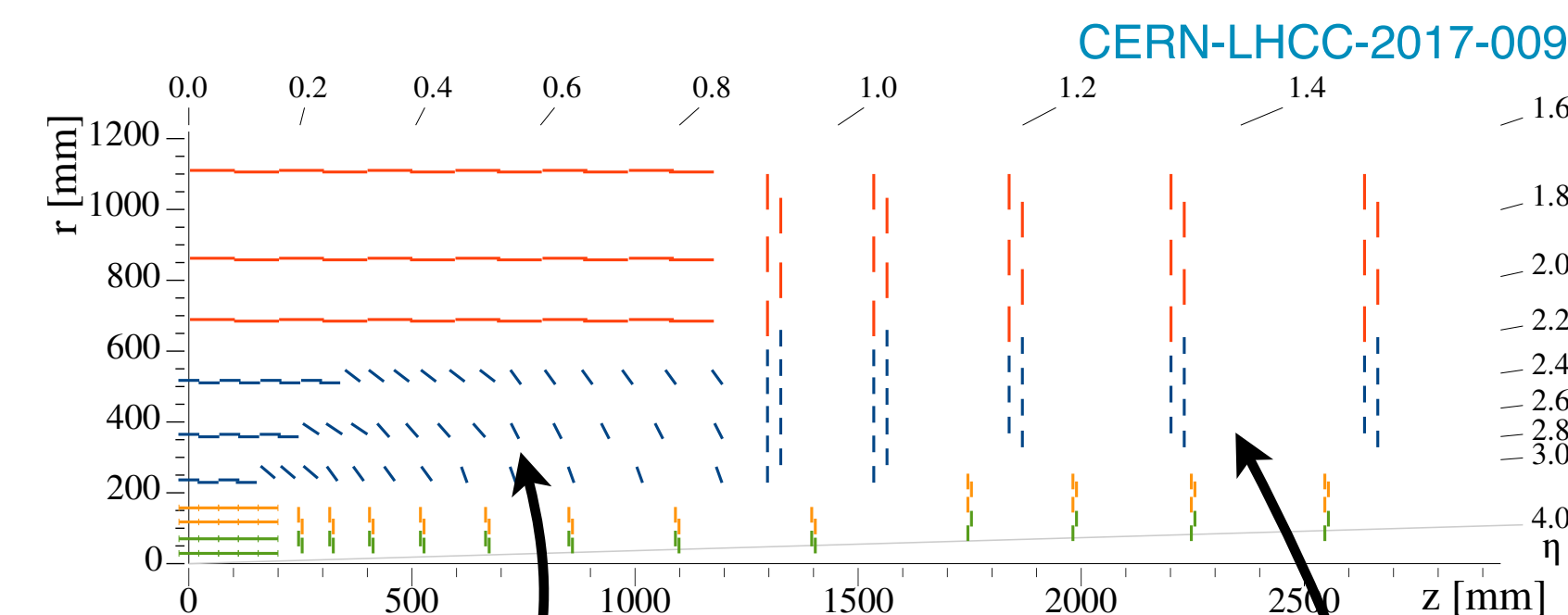


- Common CMS-ATLAS RD53 pixel readout chip in 65 nm technology
- 3D pixel sensors in “layer 0” for extreme radiation hardness
  - Shorter drift time  $\Rightarrow$  more charge collected before trapping  $\Rightarrow$  higher S/N
  - Good performance up to  $1.9 \times 10^{16} \text{ n}_{eq}/\text{cm}^2$
- Sensors production ongoing, other module components in pre-production, with planned completion 2027

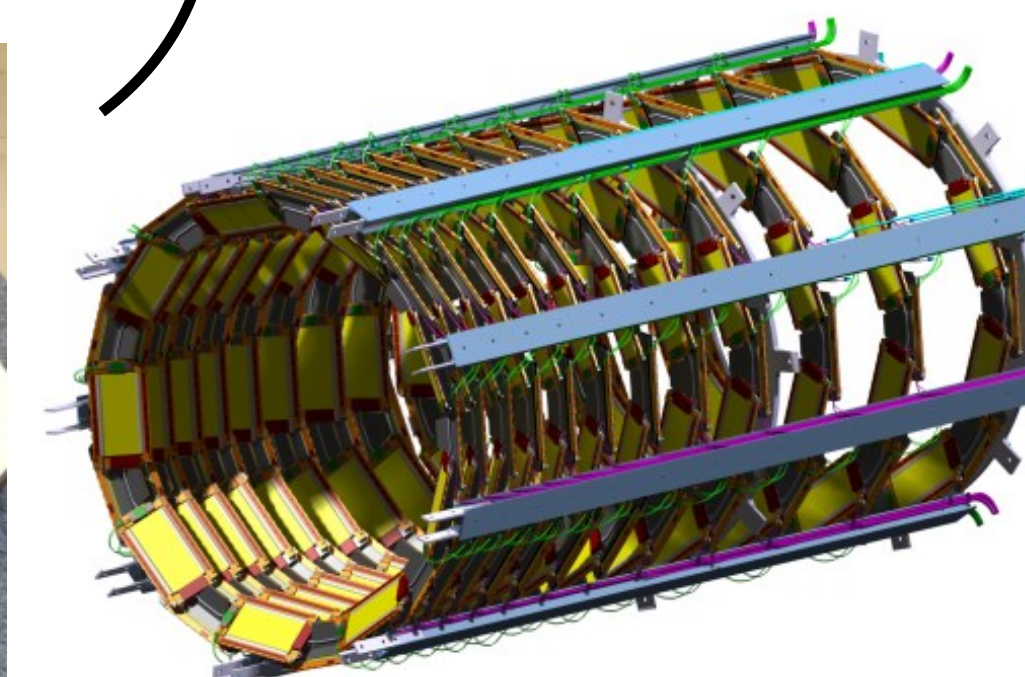
# CMS tracker



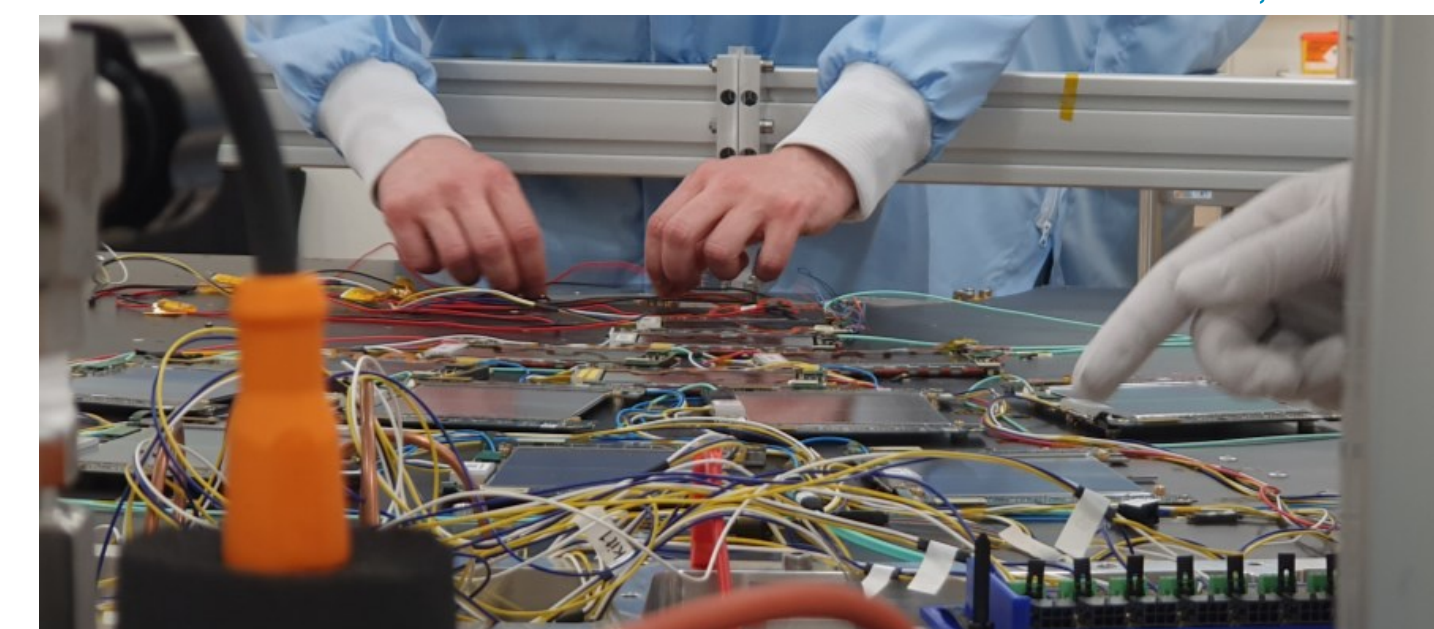
- 3D sensors in pixel layer 1, planar sensors elsewhere, as for ATLAS
- Tilted barrel section, like ATLAS, to minimize material and increase stub efficiency at high  $\eta$
- Successful module prototyping will soon lead to pre-series orders
- Sensor production (long lead time) well underway



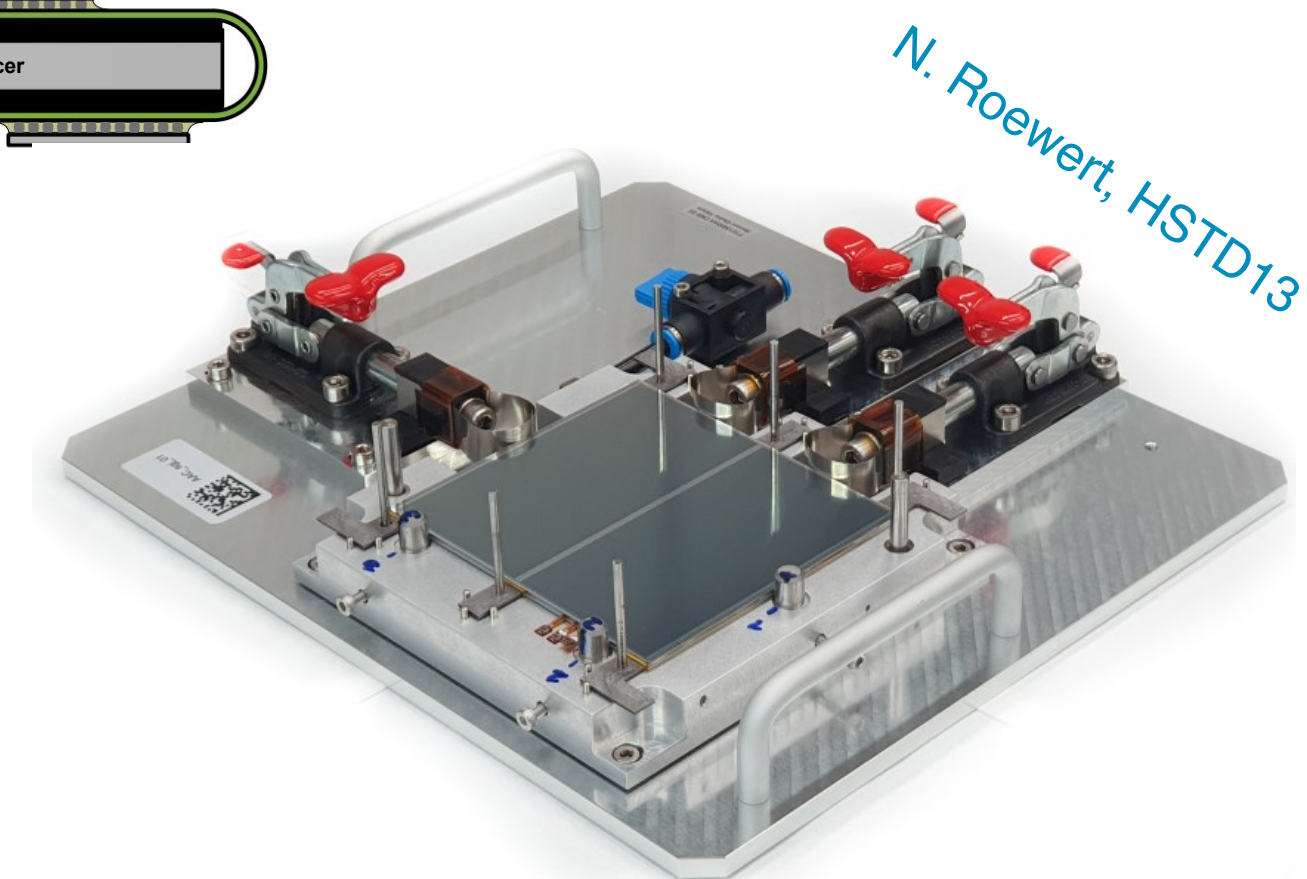
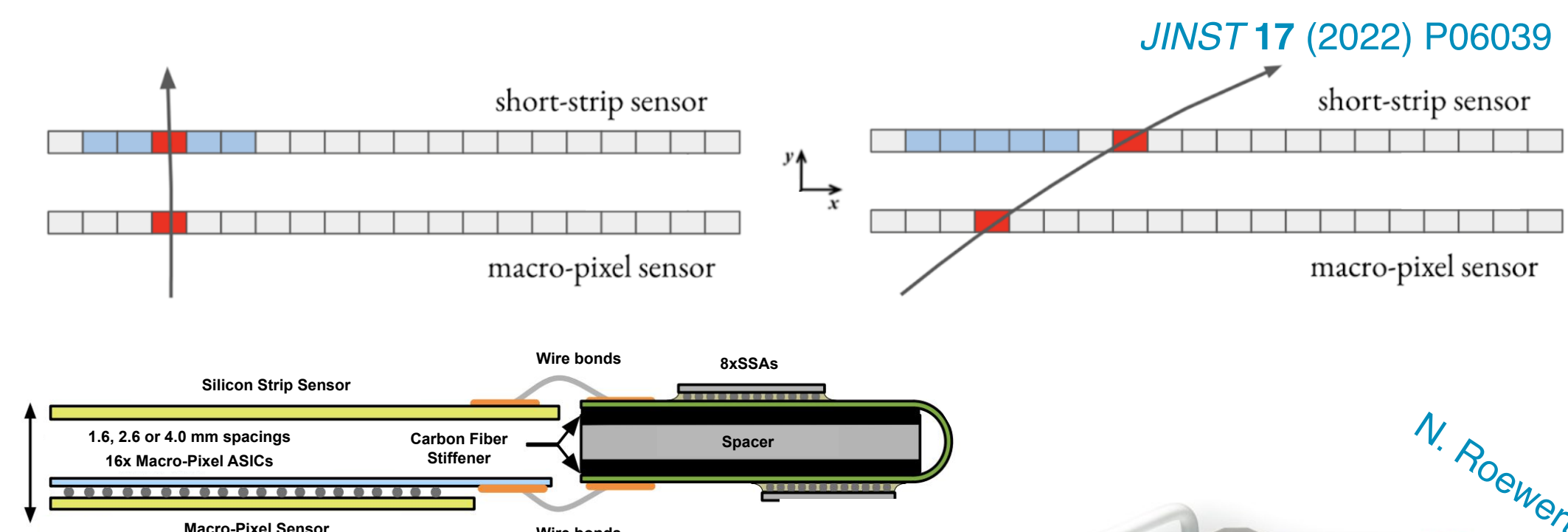
N. Roewert, HSTD13



N. Roewert, HSTD13

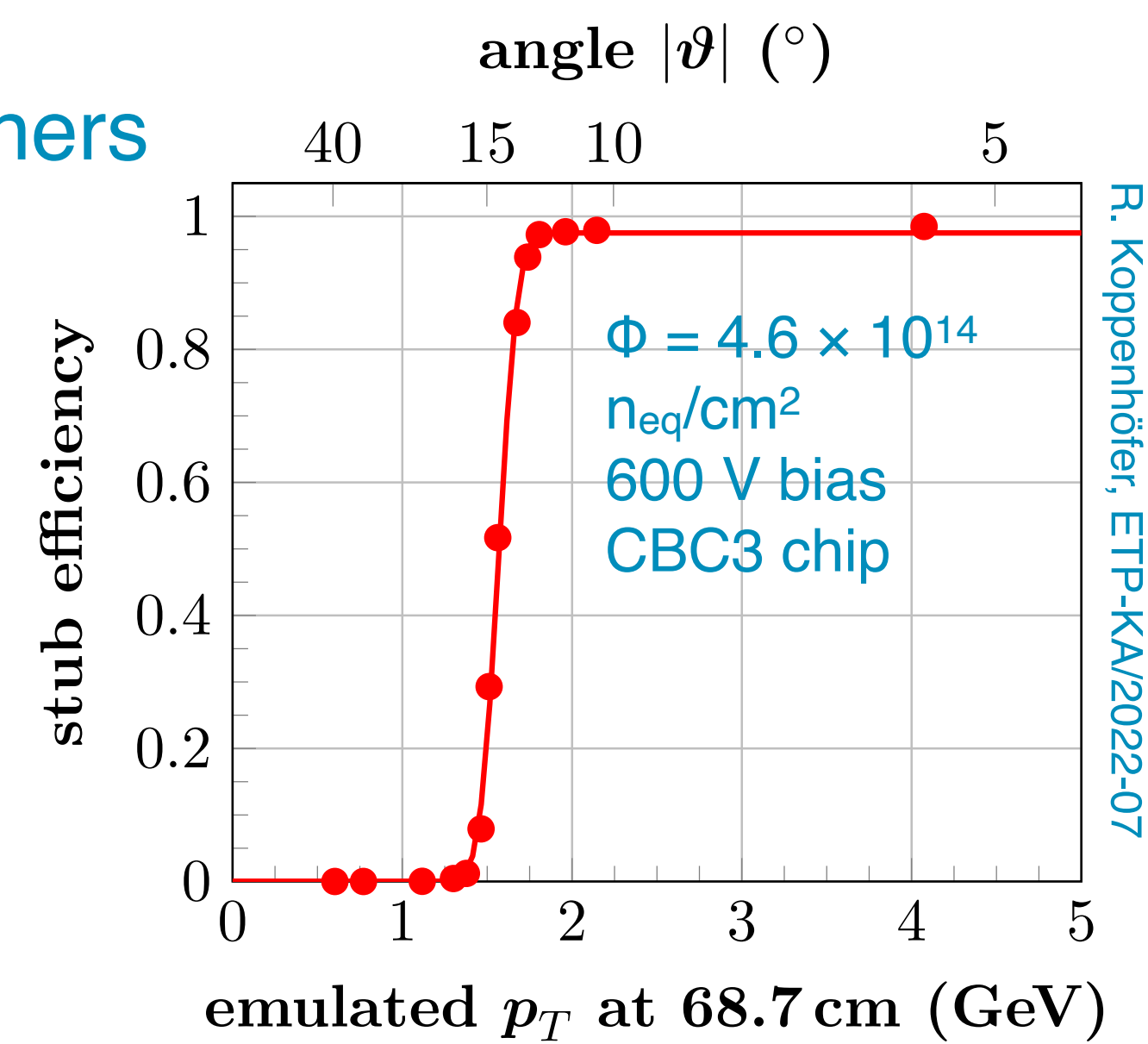


- Level-1 track trigger to enable vertex finding, particle flow, and pileup reduction at the 40 MHz interaction rate
- Double sided modules with tight tolerance on misalignment
- Carbon fiber (CF) reinforced polymer stiffeners with good thermal conductivity
- Al-CF spacers
- Binary strip readout, digitized pixel analog readout for better sensitivity to HSCPs



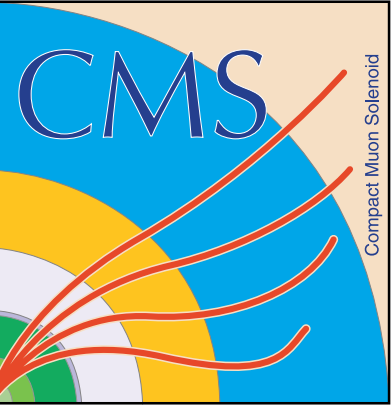
N. Roewert, HSTD13

Misalignment (controlled by jigs like this one) well within tolerances for stub finding

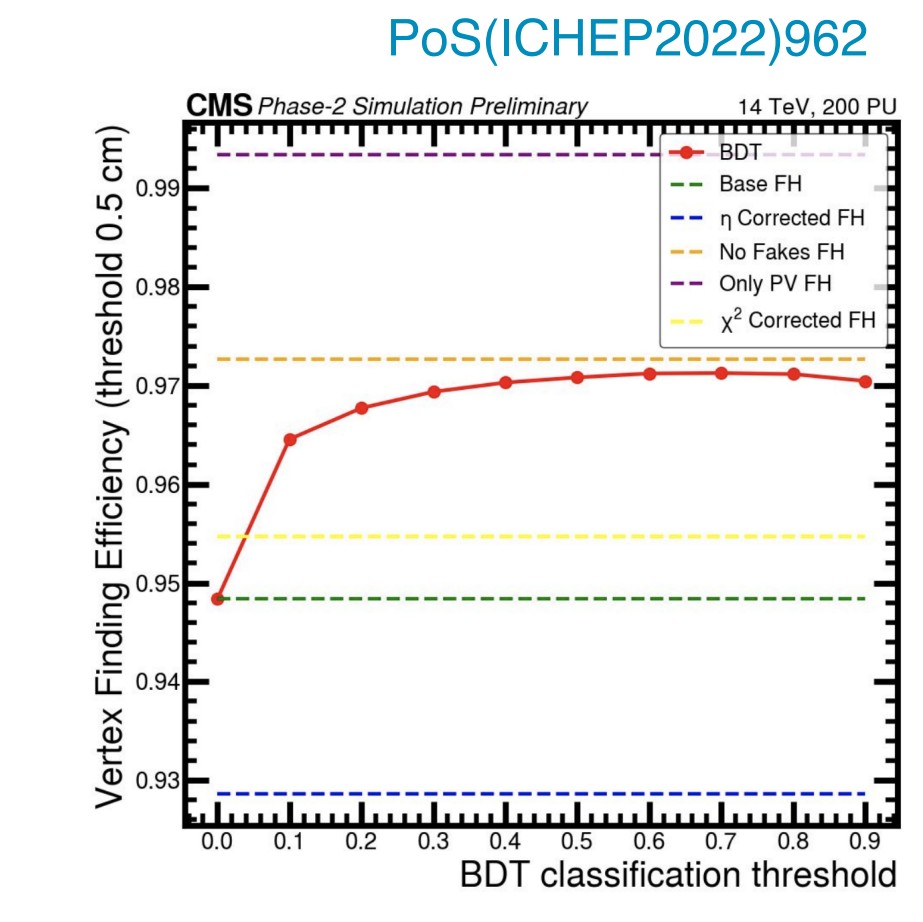
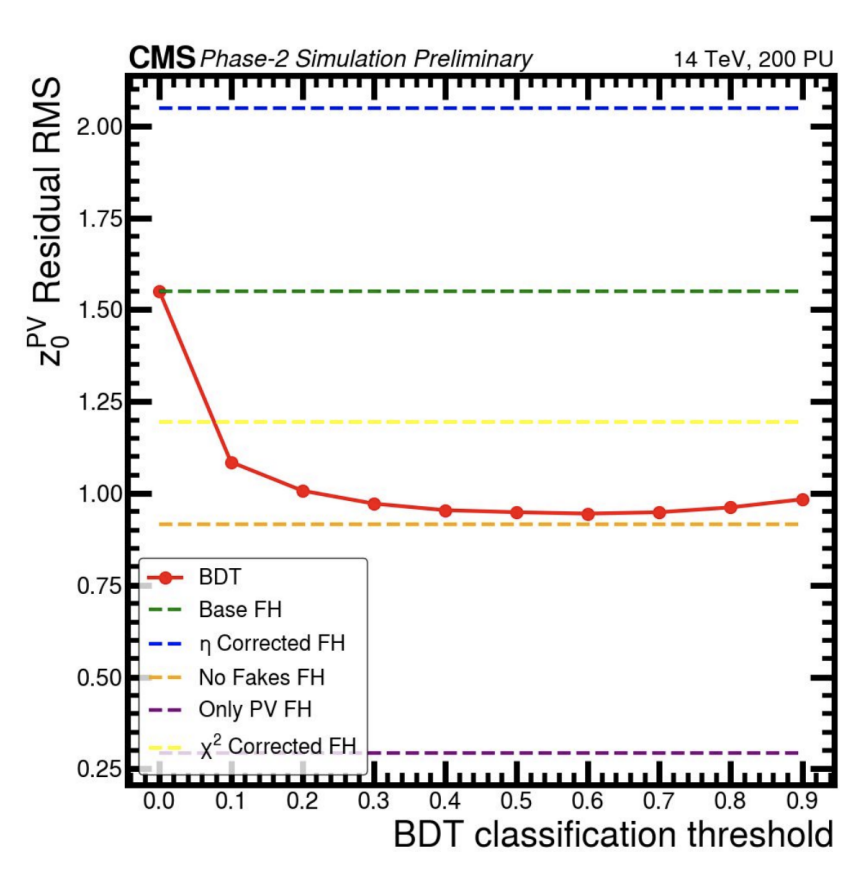
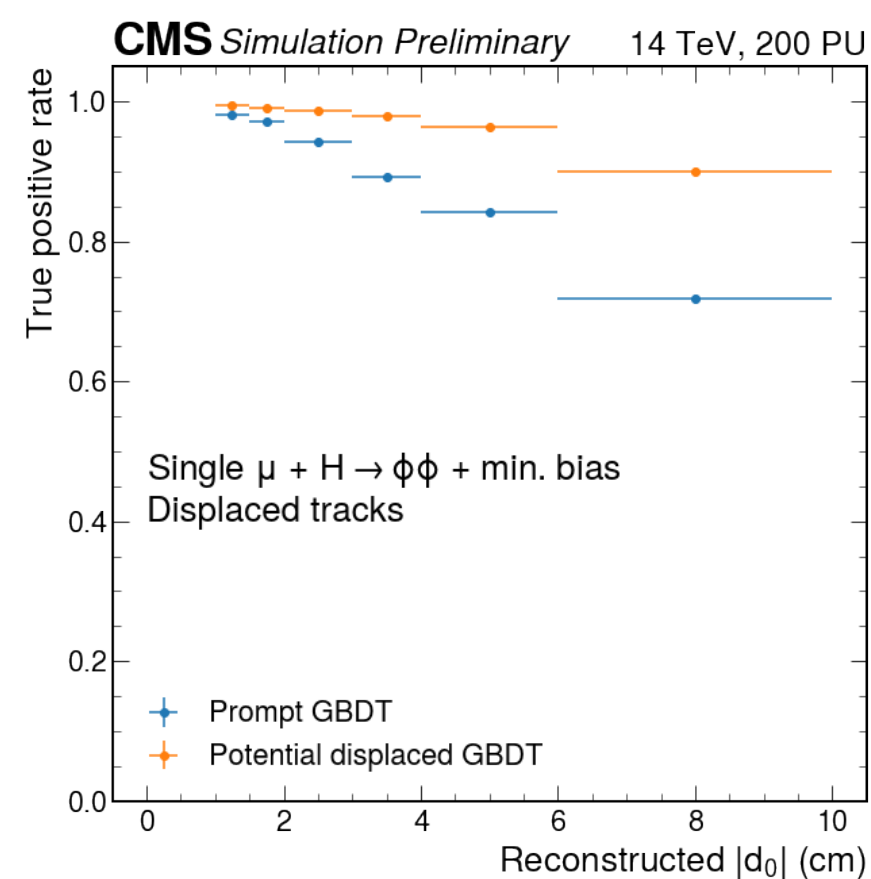
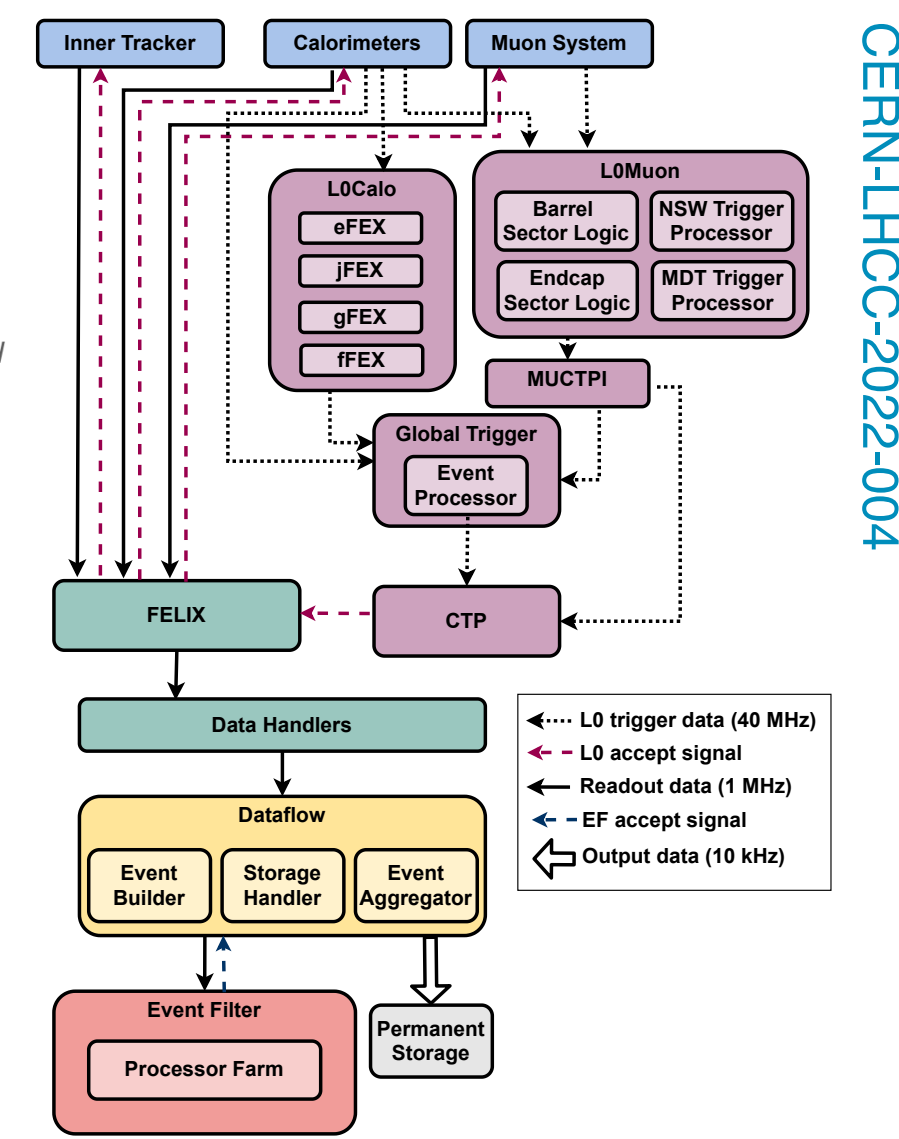
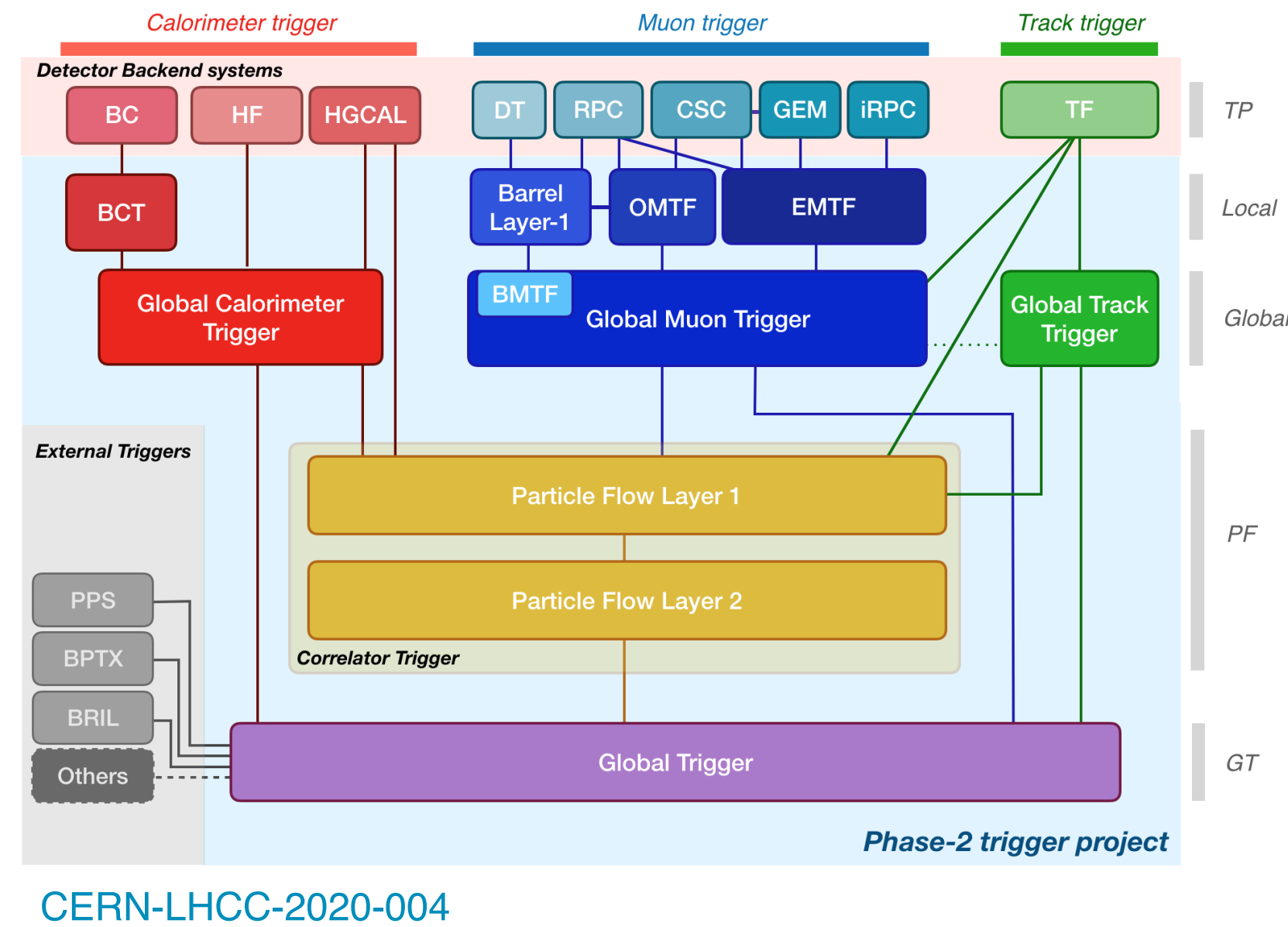


R. Koppenhöfer, ETP-KA/2022-07

# Trigger and DAQ



- Upgrades to calorimeter and muon system front end electronics to be compatible with high rate trigger
- Goal of keeping physics object  $p_T$  thresholds the same as currently
- Ability to use ML and PF in FPGA trigger boards
- Modern heterogeneous computing farms for software triggers
- Scouting for trigger monitoring and real-time analysis



# Conclusions



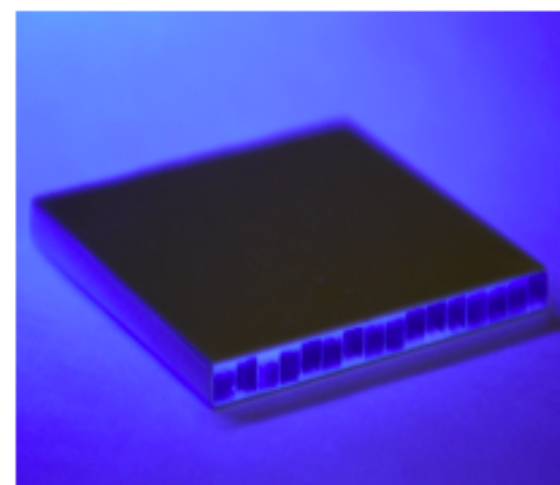
- The HL-LHC will measure the Higgs couplings and details of electroweak symmetry breaking not currently accessible
- To collect  $\sim 10$  times more data than the LHC in about the same wall clock time, significant detector upgrades are necessary to
  - Effectively trigger on electroweak processes
  - Survive the radiation environment
- Enormous progress has been made to design, prototype, and construct detectors that meet these challenges

# Backup



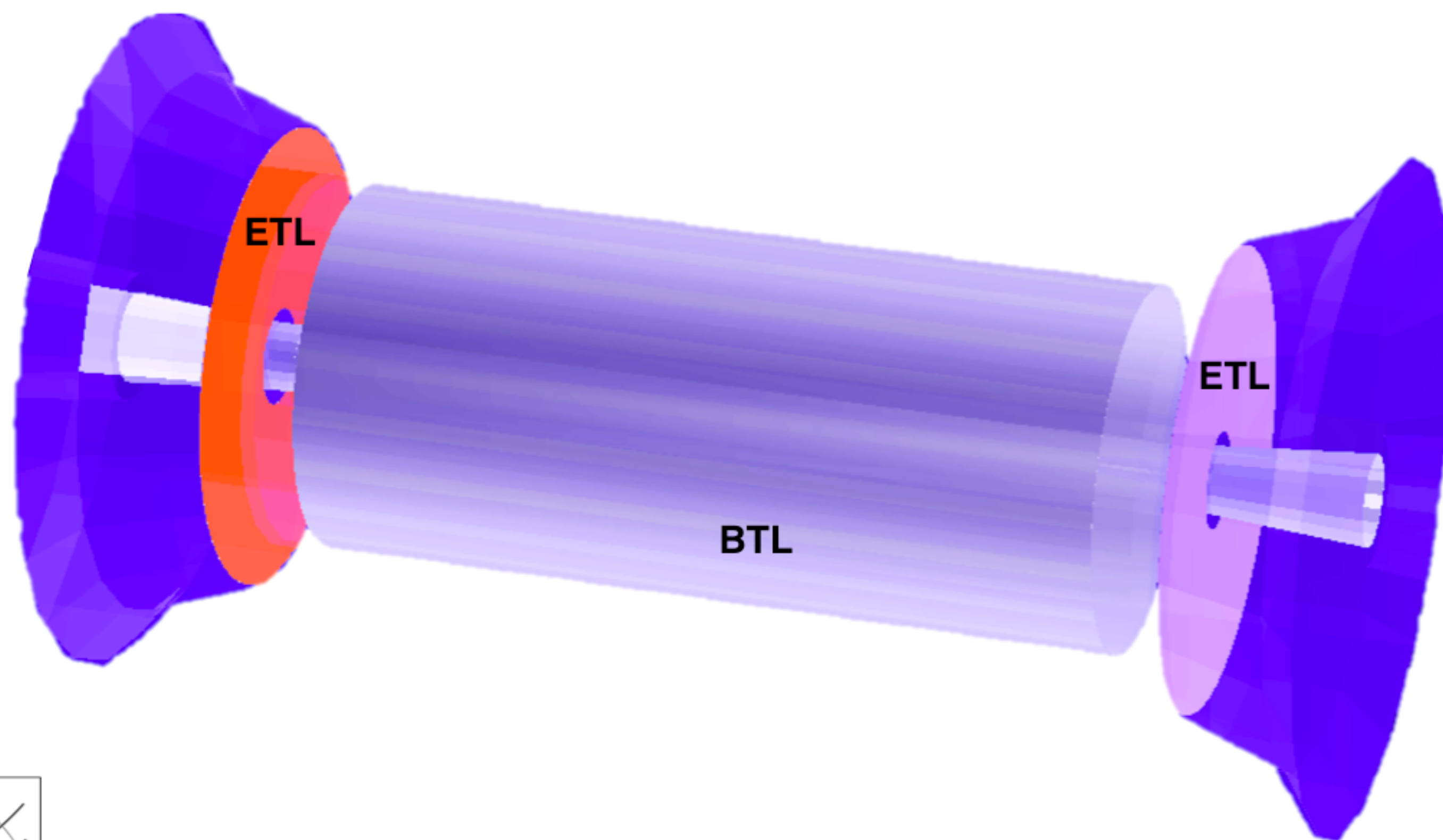
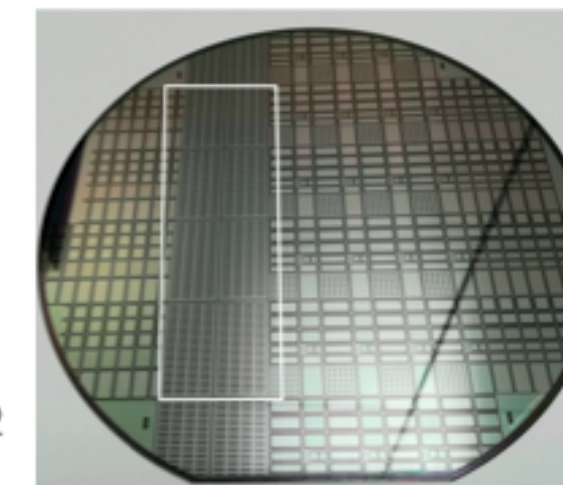
## BTL: LYSO bars + SiPM readout:

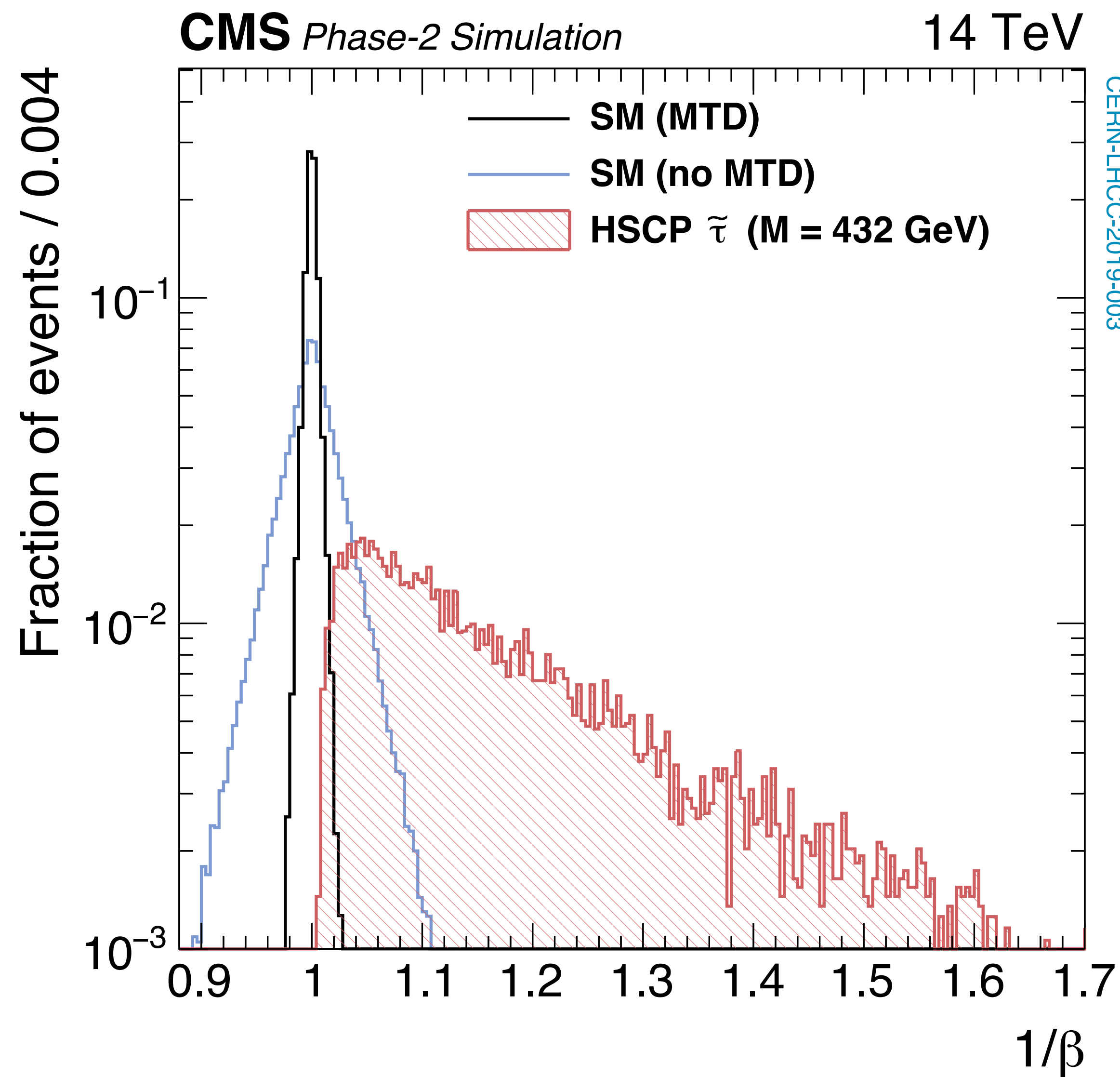
- TK / ECAL interface:  $|\eta| < 1.45$
- Inner radius: 1148 mm (40 mm thick)
- Length:  $\pm 2.6$  m along z
- Surface  $\sim 38$  m<sup>2</sup>; 332k channels
- Fluence at  $4 \text{ ab}^{-1}$ :  $2 \times 10^{14} n_{\text{eq}}/\text{cm}^2$



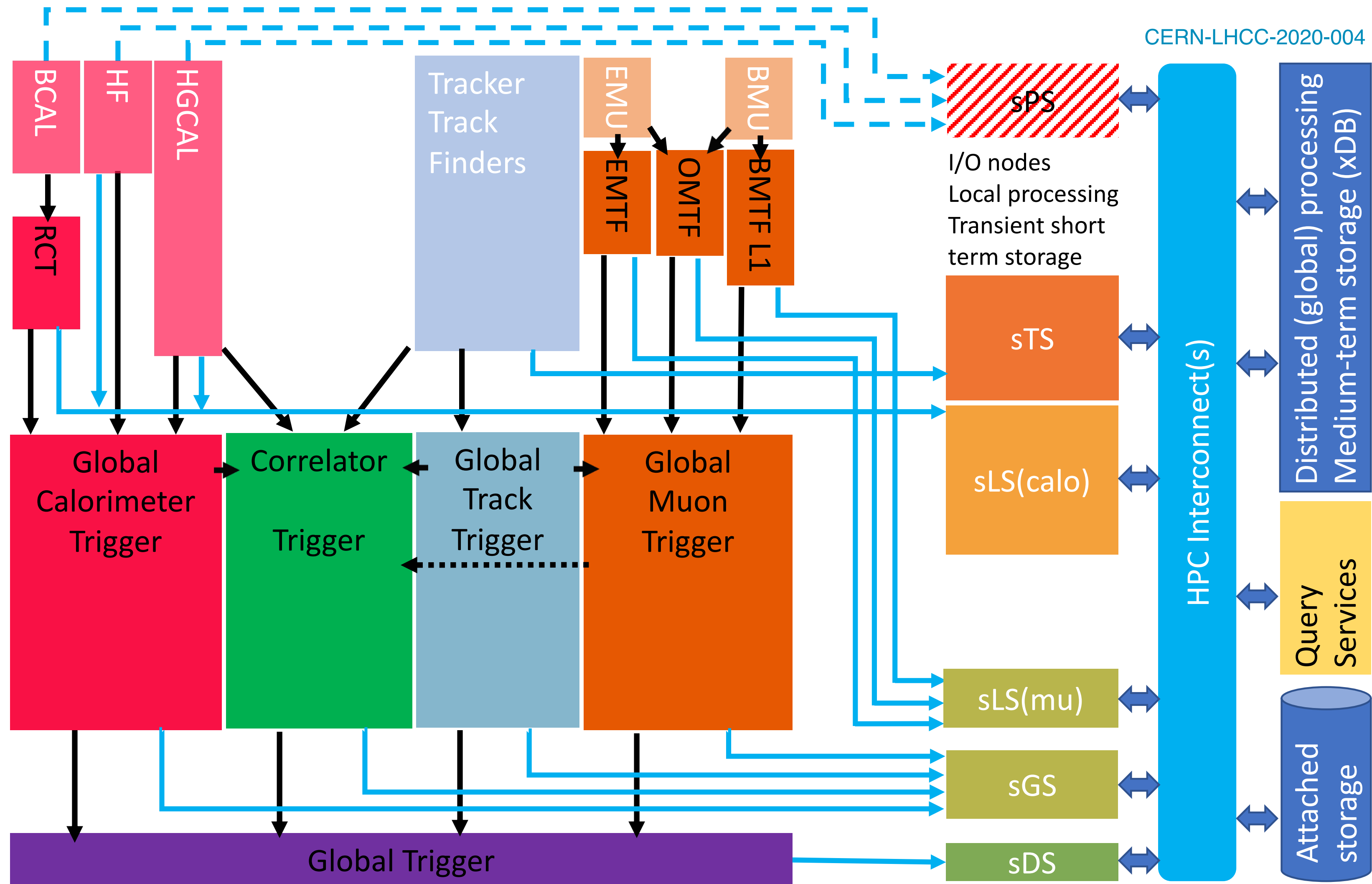
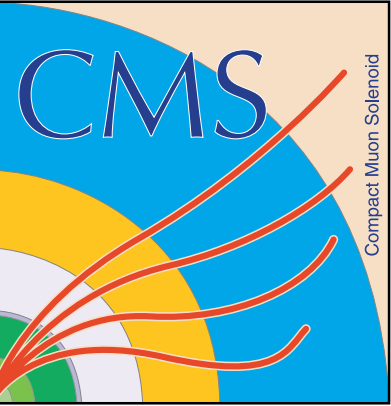
## ETL: Si with internal gain (LGAD):

- On the CE nose:  $1.6 < |\eta| < 3.0$
- Radius:  $315 < R < 1200$  mm
- Position in z:  $\pm 3.0$  m (45 mm thick)
- Surface  $\sim 14$  m<sup>2</sup>;  $\sim 8.5$ M channels
- Fluence at  $4 \text{ ab}^{-1}$ : up to  $2 \times 10^{15} n_{\text{eq}}/\text{cm}^2$





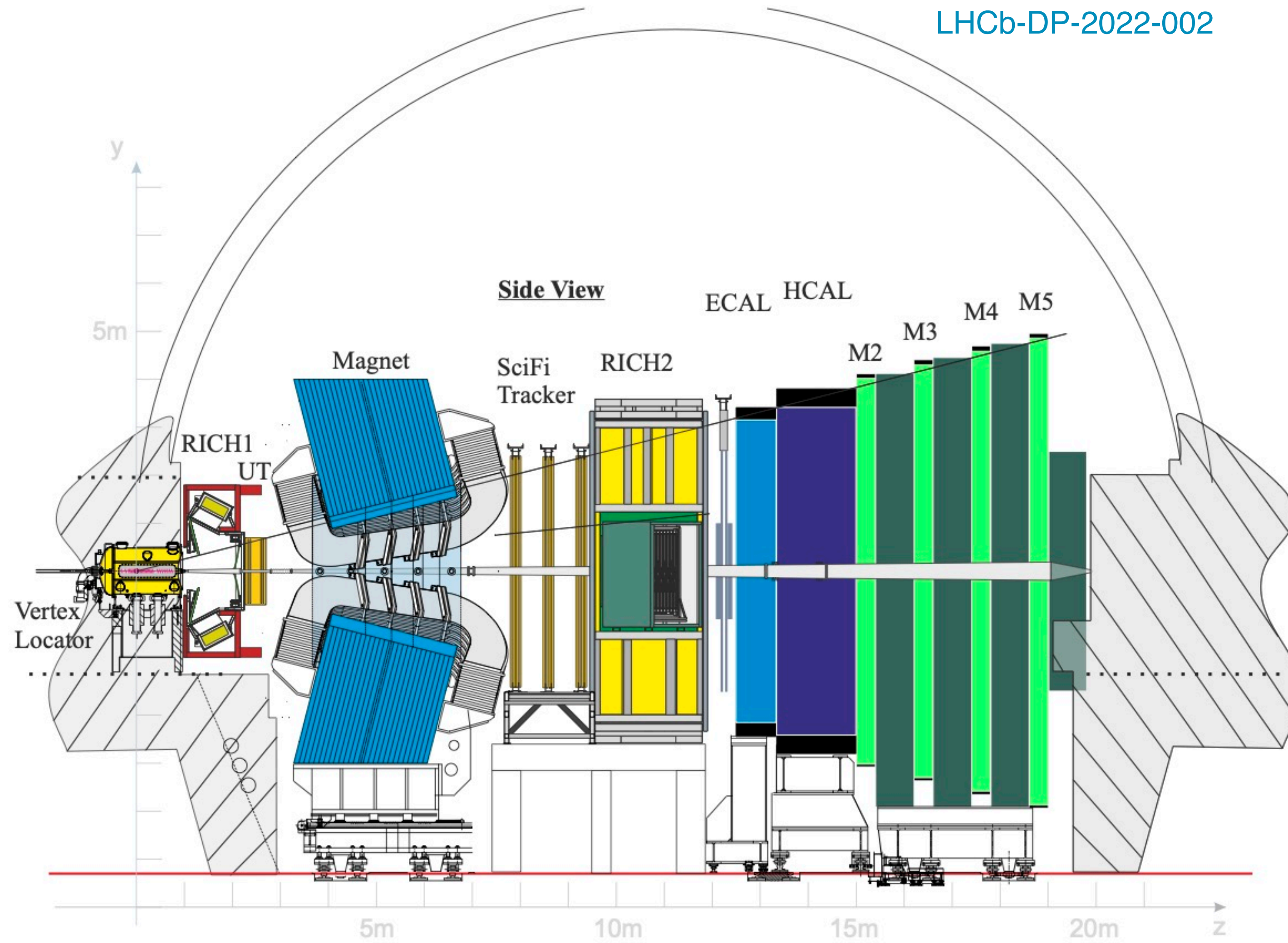
# CMS scouting system



# LHCb upgrades



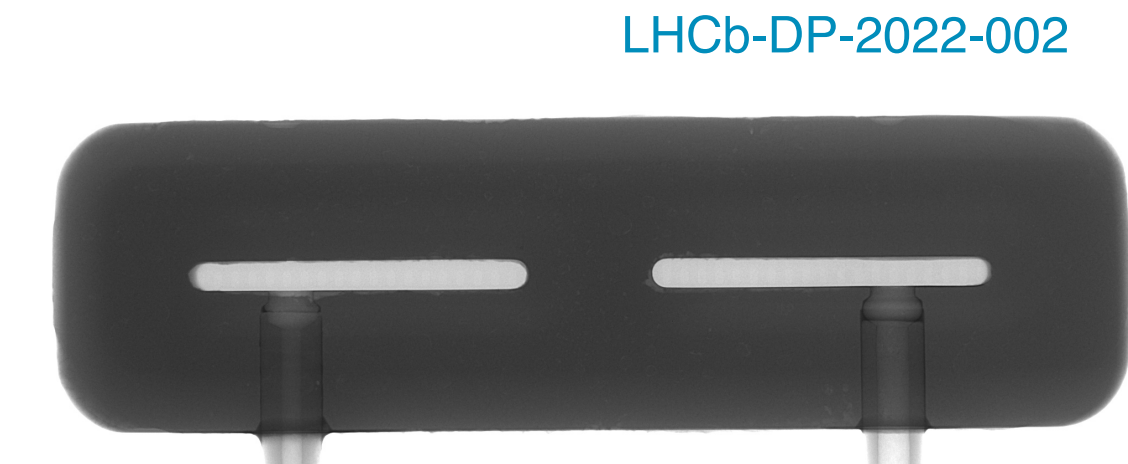
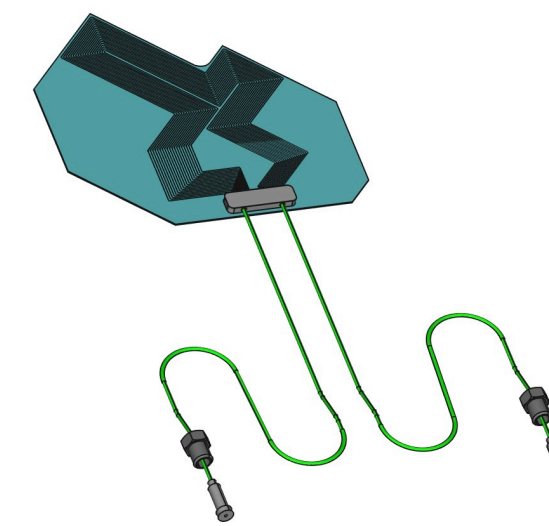
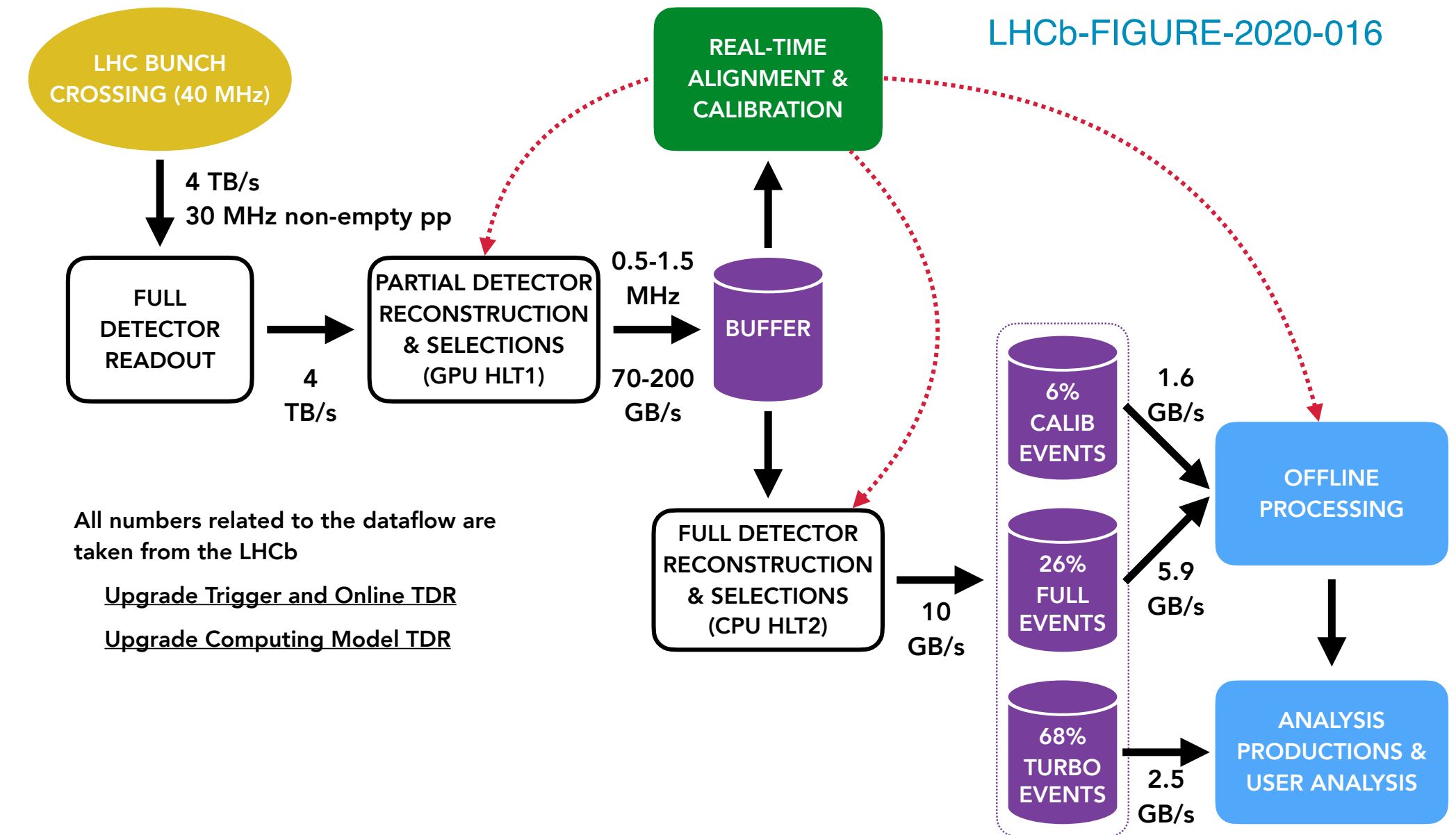
LHCb-DP-2022-002



# LHCb upgrades



- Upgrade to handle increased luminosity in Run 3 already active
- Highlights of Upgrade 1
  - Triggerless system (no L1 hardware trigger, only GPU/CPU event builder and high level trigger)
  - Real-time analysis: alignment and calibration applied at the HLT such that HLT objects are “offline” quality
  - Triggers must be highly analysis specific to reduce enormous background of events with loosely identified B hadrons
- CO<sub>2</sub> silicon microchannel cooling for the VELO which operates inside the beampipe (under vacuum) about 5 mm from the beamline



LHCb-DP-2022-002